

# AW32002 Single Cell Li-ion Battery Charger with Power Path Management and Full USB Compliance

## Features

- Charge Voltage Regulation Accuracy:  $\pm 0.5\%$  (  $0^{\circ}\text{C}$  to  $50^{\circ}\text{C}$  )
- Charge Current Accuracy:  $\pm 5\%$
- Maximum 28V Input Voltage Rating with Over-Voltage Protection
- Complete Charge Process with Pre-Charge, Fast Charge and Constant Voltage Regulation
- Programmable Charge Parameters Through I<sup>2</sup>C Compatible Interface
- Programmable Charge Termination and Autonomous Recharge
- Wide Range of Fast Charge Current: 8mA~500mA
- Strong and Robust Protection: V<sub>IN</sub> OVP, Battery OVP, OCP, Reverse Leakage Protection, Short Protection, Thermal Protection, PCB Over Temperature Protection
- BATFET Control to Support Shipping Mode
- System Reset Function
- Fully Integrated Power Path Management
- Ultra-low Battery Leakage Current to Support Shipping Mode
- WLCSP 1.68mm×1.68mm×0.63mm-9B, 0.5mm Pitch Package
- 7-bit slave address (A7~A1) is 1001001 binary(0x49H)
- IEC62368-1 Approved-File No.BE-37454

## Applications

- Smart Handheld Devices
- Wearable Devices
- Smart Watches
- Fitness Accessories

## General Description

The AW32002 is a highly-integrated Li-Ion/Li-Polymer battery linear charger with system power path management. The charge process of AW32002 includes: Pre-Charge, Fast Charge and Constant Voltage Regulation. The charge parameters and operating modes are programmable through I<sup>2</sup>C interface. The charge process runs automatically and recharging occurs when the battery voltage drops below V<sub>BAT\_REG</sub>-V<sub>RECH</sub> after the charge done status.

The AW32002 is targeted at space limited portable applications. The chip can take input power from either an AC adaptor or a USB port to supply the system load and charge the battery. Meanwhile, the chip provides system short circuit protection function by limiting the current from the input to the system and the battery to the system. These features are effective to protect the battery or chip from damage. The parameters of input current limit, the discharge current limit and safety timer can be programmed by the I<sup>2</sup>C interface. Additionally, input over voltage protection, input under voltage lockout and input headroom voltage are integrated for good input source detection.

AW32002 separates the charging route from the system power supply to fulfill the power management function. The system power supply is at first priority with no dependency on battery existence. Once a bad power-limited adapter appears at the input, AW32002 would reduce the charging current firstly. If the system load is still too heavy for input source, AW32002 will reduce the input-system current to prevent the input source from being pulled down. Under this circumstance, if the system voltage drops 30mV below the battery voltage, the battery to system supply route will be fully turned on to power the system load, which is supplement mode.

## Typical Application Circuit

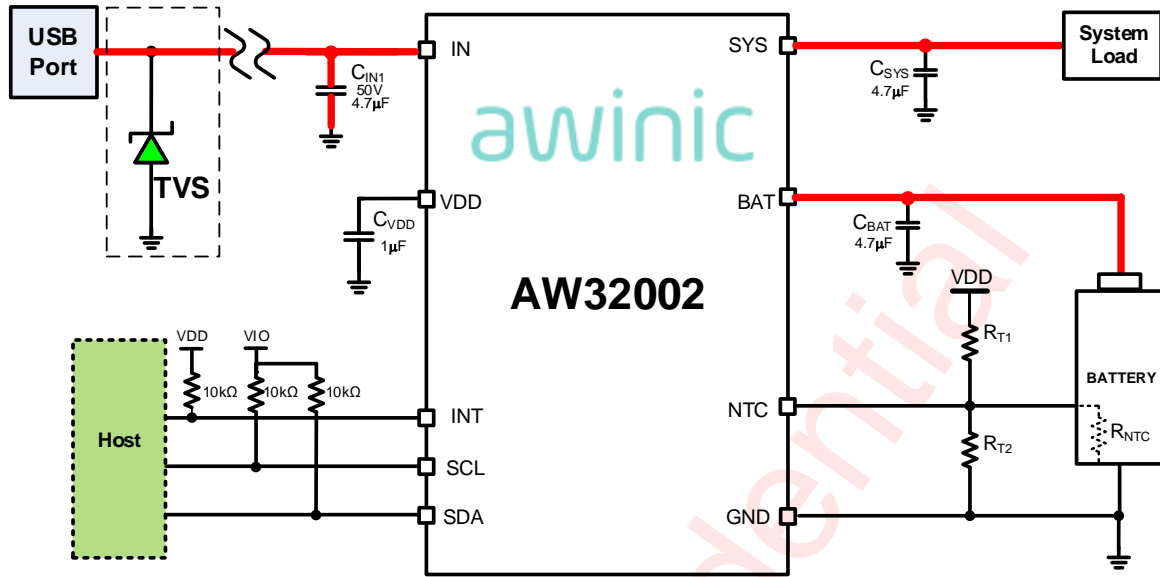


Figure 1 Typical Application Circuit of AW32002

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## Pin Configuration and Top Mark

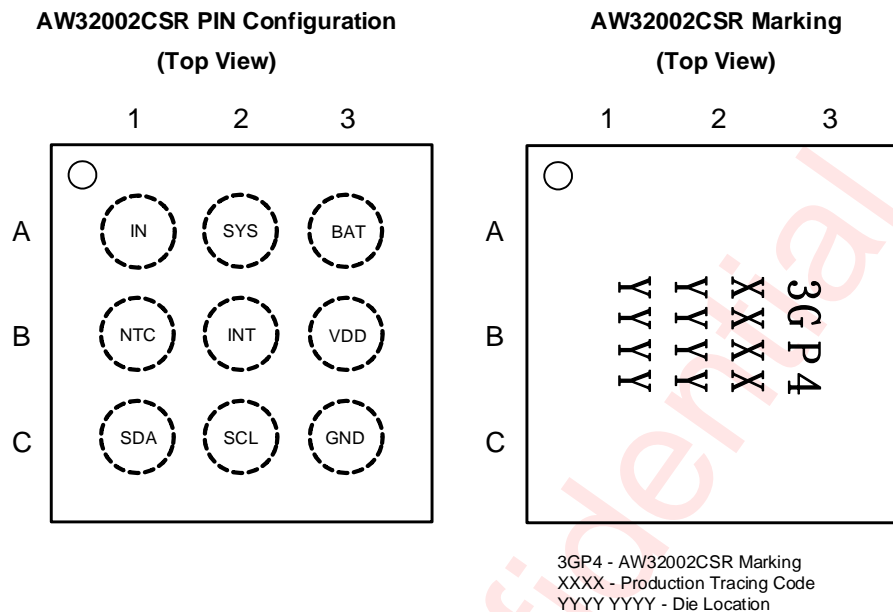


Figure 2 Pin Configuration and Top Mark

## Pin Definition

Pin No.	Pin Name	Description
A1	IN	Input power pin. Bypass with a 4.7 $\mu$ F capacitor to GND.
A2	SYS	System power supply pin. Bypass with a 4.7 $\mu$ F capacitor to GND.
A3	BAT	Battery pin. Bypass with a 4.7 $\mu$ F capacitor to GND.
B1	NTC	Temperature sense input. Connect a negative temperature coefficient thermistor. Program the hot and cool temperature window with resistor dividers from VDD to GND, and NTC is the middle node. Pull NTC to VDD if NTC function is not used. If NTC function is unused, it is suggested to disable the NTC function and tie the NTC port to VDD for decreasing leakage current of battery, because PCB_OTP is default.
B2	INT	Interrupt output. The INT pin can send charge status and fault interrupt to the host. This pin is also used to disconnect the system from battery, and awake the chip from shipping mode. If INT is unused, it is suggested to tie INT to VDD by resistor.
B3	VDD	Internal power supply pin. Bypass with a 1 $\mu$ F capacitor to GND. No external load is allowed.
C1	SDA	I <sup>2</sup> C Interface serial date.
C2	SCL	I <sup>2</sup> C Interface clock.
C3	GND	Ground.

## Ordering Information

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW32002CSR	-40°C~85°C	WLCSP 1.68mm×1.68mm-9B	3GP4	MSL1	ROHS+HF	3000 units/ Tape and Reel

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## Absolute Maximum Ratings<sup>(NOTE1)</sup>

PARAMETERS		MIN	MAX	UNIT
Input voltage range $V_{IN}$ (with respect to GND)	IN	-0.3	28	V
NTC voltage range $V_{NTC}$ (with respect to GND)	NTC	-0.3	$V_{VDD}+0.3$	V
Other pins voltage range (with respect to GND)	SYS, BAT, INT, VDD, SCL, SDA	-0.3	6	V
Operating free-air temperature range		-40	85	°C
Operating junction temperature $T_J$		-40	150	°C
Storage temperature $T_{STG}$		-65	150	°C
Lead temperature (Soldering 10 seconds)			260	°C

NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should be within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

## ESD Rating and Latch Up

PARAMETERS	VALUE	UNIT
HBM (Human Body Model) <sup>(NOTE 2)</sup>	±2	kV
CDM <sup>(NOTE 3)</sup>	±1.5	kV
Latch-Up <sup>(NOTE 4)</sup>	+IT: 200 -IT: -200	mA

NOTE2: The human body model is a 100pF capacitor discharged through a 1.5kΩ resistor into each pin. Test method: ESDA/JEDEC JS-001-2017

NOTE3: Test method: ESDA/JEDEC JS-002-2018

NOTE4: Test method: JESD78E

## Recommended Operating Conditions

PARAMETERS	MIN	NORM	MAX	UNIT
Supply voltage range $V_{IN}$	4		5.5	V
Supply current $I_{IN}$			550	mA
Discharge current $I_{BAT}$			3.2	A
Charge current $I_{CHG}$	8		512	mA
Battery regulated voltage $V_{BAT\_REG}$	3.6		4.545	V
Operating junction temperature $T_J$	-40		125	°C

## Thermal Information

PARAMETERS	VALUE	UNIT
Junction-to-ambient thermal resistance $\theta_{JA}$	122	°C/W

## Electrical Characteristics

$V_{IN}=5V$ ,  $V_{BAT}=3.5V$ ,  $T_J=25^{\circ}C$  for typical values (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>INPUT SOURCE AND BATTERY PROTECTION</b>						
$V_{IN\_UVLO}$	UVLO threshold voltage, entry UVLO	$V_{IN}$ falling	3.5	3.6	3.7	V
	Hysteresis for UVLO	$V_{IN}$ rising		300		mV
$T_{DGL\_UVLO}$	Exit deglitch time for $V_{IN}$ UVLO	Exits $V_{IN}$ UVLO		30		ms
$V_{IN\_OVP}$	$V_{IN}$ OVP threshold voltage	$V_{IN}$ rising	5.85	6	6.15	V
	$V_{IN}$ OVP hysteresis	$V_{IN}$ falling from above $V_{IN\_OVP}$		350		mV
$T_{DGL\_OVP}$	Exit deglitch time for $V_{IN\_OVP}$	Exits $V_{IN}$ OVP		30		ms
$V_{BAT}$	BAT input voltage				4.6	V
$V_{BAT\_UVLO}$	UVLO threshold voltage for BAT voltage, $V_{BAT}$ falling, entry UVLO	REG01H[2:0]=000	2.33	2.43	2.53	V
		REG01H[2:0]=100	2.64	2.76	2.88	V
		REG01H[2:0]=111	2.93	3.03	3.13	V
	Hysteresis voltage	$V_{BAT\_UVLO}=2.76V$		190		mV
$V_{HDRM}$	Input vs. battery voltage headroom threshold	$V_{IN}$ rising	80	130	170	mV
	Input vs. battery voltage headroom threshold hysteresis	$V_{IN}$ falling		60		mV
<b>CHARGE PROCESS</b>						
$V_{BAT\_PRE}$	Pre-charge to fast charge threshold	REG04H[1]=1, $V_{BAT}$ rising	2.9	3.0	3.1	V
		REG04H[1]=0, $V_{BAT}$ rising	2.7	2.8	2.9	V
	Fast charge to pre-charge threshold	$V_{BAT}$ falling		200		mV
$V_{BAT\_REG}$	Battery charge voltage regulation voltage	REG04H[7:2]=000000, $V_{BAT\_REG}=3.6V$	3.585	3.600	3.615	V
		REG04H[7:2]=101000, $V_{BAT\_REG}=4.2V$	4.180	4.200	4.220	V
		REG04H[7:2]=110100, $V_{BAT\_REG}=4.38V$	4.360	4.380	4.400	V
		REG04H[7:2]=111110, $V_{BAT\_REG}=4.53V$	4.507	4.530	4.553	V
$V_{RECH}$	Recharge threshold voltage	REG04H[0]=0, $V_{BAT\_REG}=4.2V$ , below $V_{BAT\_REG}$	60	100	140	mV
		REG04H[0]=1, $V_{BAT\_REG}=4.2V$ , below $V_{BAT\_REG}$	160	200	240	mV
	Deglitch time for $V_{RECH}$	$V_{BAT}$ falling below $V_{RECH}$ after charge termination		130		ms
$V_{BAT\_OVP}$	Battery OVP threshold voltage	$V_{BAT}$ threshold over $V_{BAT\_REG}$ to turn off charger during charging		130		mV
	$V_{BAT\_OVP}$ hysteresis			50		mV

**Electrical Characteristics (Continued)**V<sub>IN</sub>=5V, V<sub>BAT</sub>=3.5V, T<sub>J</sub>=25°C for typical values (unless otherwise noted).

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>POWER PATH MANAGEMENT</b>						
V <sub>SYS_REG</sub>	Regulated system output voltage	V <sub>IN</sub> =5.0V, REG07H[3:0]=0000, R <sub>SYS</sub> =100Ω, I <sub>CHG</sub> =0A, V <sub>SYS_REG</sub> =4.2V	4.11	4.20	4.29	V
		V <sub>IN</sub> =5.0V, REG07H[3:0]=1000, R <sub>SYS</sub> =100Ω, I <sub>CHG</sub> =0A, V <sub>SYS_REG</sub> =4.6V	4.51	4.60	4.69	V
		V <sub>IN</sub> =5.3V, REG07H[3:0]=1111, R <sub>SYS</sub> =100Ω, I <sub>CHG</sub> =0A, V <sub>SYS_REG</sub> =4.95V	4.85	4.95	5.05	V
I <sub>IN_LIM</sub>	Input current limit	REG00H[3:0]=0000, I <sub>IN_LIM</sub> =50mA	30	45	60	mA
		REG00H[3:0]=0011, I <sub>IN_LIM</sub> =140mA	112	125	140	mA
		REG00H[3:0]=1001, I <sub>IN_LIM</sub> =320mA	275	296	320	mA
		REG00H[3:0]=1111, I <sub>IN_LIM</sub> =500mA	440	460	500	mA
V <sub>IN_DPM</sub>	Dynamic input power management clamp voltage	REG00H[7:4]=0000, V <sub>IN_DPM</sub> =3.88V	3.68	3.88	4.18	V
		REG00H[7:4]=1000, V <sub>IN_DPM</sub> =4.52V	4.32	4.52	4.82	V
		REG00H[7:4]=1111, V <sub>IN_DPM</sub> =5.08V	4.88	5.08	5.35	V
R <sub>ON_Q1</sub>	IN to SYS switches on resistance	V <sub>IN_DPM</sub> =3.88V, V <sub>IN</sub> =4.5V, I <sub>SYS</sub> =100mA		300	350	mΩ
R <sub>ON_Q2</sub>	BAT to SYS switch on resistance	V <sub>IN</sub> <2V, V <sub>BAT</sub> =3.5V, I <sub>SYS</sub> =100mA		103	115	mΩ
I <sub>IN_Q</sub>	Input quiescent current (not include the current from external NTC resistor)	V <sub>IN</sub> =5V, EN_HIZ=0, CEB=0, <b>(charge enable)</b> , I <sub>CHG</sub> =0, I <sub>SYS</sub> =0		1.7	3.2	mA
		V <sub>IN</sub> =5V, EN_HIZ=0, CEB=1, <b>(charge disabled)</b> , I <sub>CHG</sub> =0, I <sub>SYS</sub> =0		1.5	3.0	mA
I <sub>BAT_Q</sub>	Battery quiescent current (not include the current from external NTC resistor)	V <sub>IN</sub> =5V, CEB=0, charge done, I <sub>CHG</sub> =0, I <sub>SYS</sub> =0		58	80	μA
		V <sub>IN</sub> =0, CEB=1, V <sub>BAT</sub> =4.35V, DIS_PCB_OTP=1, I <sub>SYS</sub> =0		21	32	μA
		V <sub>IN</sub> =0, CEB=1, V <sub>BAT</sub> =4.35V, DIS_PCB_OTP=0, I <sub>SYS</sub> =0		27	38	μA
		V <sub>IN</sub> =0, CEB=1, V <sub>BAT</sub> =4.35V, DIS_PCB_OTP=0, I <sub>SYS</sub> =0, enable watchdog		28	38	μA
		V <sub>BAT</sub> =4.5V, V <sub>IN</sub> =V <sub>SYS</sub> =0, FET_DIS=1, shipping mode			1	μA
I <sub>SYS-BAT_LKG</sub>	SYS reverse to BAT switch leakage	V <sub>SYS</sub> =4.60V, V <sub>IN</sub> =5V, V <sub>BAT</sub> =0, CEB=1, EN_HIZ=1, charge disabled			1	μA
I <sub>DSCHG</sub>	BAT FET discharge current limit	REG03H[7:4]=0001, I <sub>DSCHG</sub> =400mA	300	440	500	mA
		REG03H[7:4]=1001, I <sub>DSCHG</sub> =2000mA		2000		mA
V <sub>FWD</sub>	Ideal diode forward voltage in supplement mode	50mA discharge current		30		mV

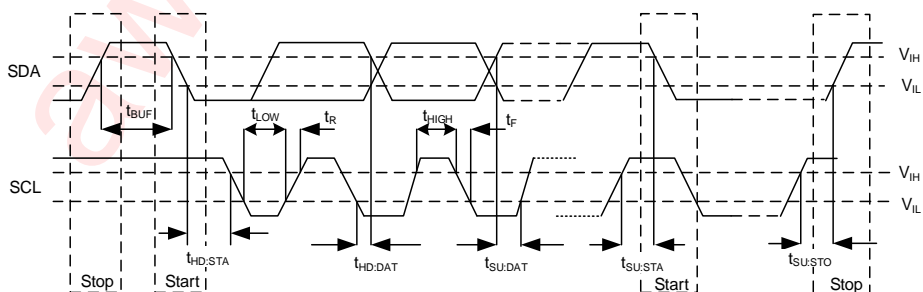
**Electrical Characteristics (Continued)** $V_{IN}=5V$ ,  $V_{BAT}=3.5V$ ,  $T_J=25^\circ C$  for typical values (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>CHARGE CURRENT</b>						
I <sub>CHG</sub>	Output charge regulation current programmable range	$V_{BAT\_PRE} < V_{BAT} < V_{BAT\_REG}$ , REG0BH[7]=1, I <sub>CHG</sub> =2mA	1.5	2	2.5	mA
		$V_{BAT\_PRE} < V_{BAT} < V_{BAT\_REG}$ , REG0BH[7]=0, I <sub>CHG</sub> =8mA	6.9	8	9	mA
		$V_{BAT\_PRE} < V_{BAT} < V_{BAT\_REG}$ , REG0BH[7]=0, I <sub>CHG</sub> =96mA	89	96	103	mA
		$V_{BAT\_PRE} < V_{BAT} < V_{BAT\_REG}$ , REG0BH[7]=0, I <sub>CHG</sub> =264mA	252	264	276	mA
		$V_{BAT\_PRE} < V_{BAT} < V_{BAT\_REG}$ , REG0BH[7]=0, I <sub>CHG</sub> =456mA	434	456	478	mA
	Charge Current Regulation Accuracy	$V_{BAT}=3.8V$ , $8mA < I_{CHG} \leq 12mA$	-20		20	%
		$V_{BAT}=3.8V$ , $12mA < I_{CHG} < 264mA$	-7		7	%
		$V_{BAT}=3.8V$ , $I_{CHG} \geq 264mA$	-5		5	%
I <sub>PRE</sub>	Pre-charge current programmable range, I <sub>PRE</sub> =I <sub>TERM</sub>	$V_{BAT} < 3.0V$	1	31	mA	
I <sub>TERM</sub>	Termination charge current threshold, programmable	REG03H[3:0]=0000, I <sub>CHG</sub> =1mA	0.8	1	1.2	mA
		REG03H[3:0]=0001, I <sub>CHG</sub> =3mA	2.6	3	3.3	mA
		REG03H[3:0]=0101, I <sub>CHG</sub> =11mA	9.5	11	13	mA
		REG03H[3:0]=1111, I <sub>CHG</sub> =31mA	28	31	34	mA
T <sub>TERM</sub>	Termination deglitch time	$I_{CHG} < I_{TERM}$ , REG0CH[6]=0		3.2	s	
I <sub>DBAT</sub>	Battery detection current before charge done (sink current)	Begins after termination detected and $V_{BAT} < V_{BAT\_REG}$		0.5	mA	
T <sub>DBAT</sub>	Battery detection time			262	ms	
<b>INT</b>						
V <sub>OL_INT</sub>	Low-level output saturation voltage, INT pin	I <sub>O</sub> =5mA, sink current			0.4	V
I <sub>LKG_INT</sub>	High-level leakage current for INT	INT is in High-impedance status, V <sub>INT</sub> =5V			1	μA
T <sub>RST_DGL</sub>	INT pulled low time to reset V <sub>SYS</sub>	V <sub>INT</sub> low(default setting)		16		s
<b>I<sup>2</sup>C BUS LOGIC LEVELS AND TIMING CHARACTERISTICS</b>						
V <sub>OL</sub>	Output low threshold level	I <sub>O</sub> =5mA, sink current			0.4	V
V <sub>IL</sub>	Input low threshold level	V <sub>pull_up</sub> =1.8V, SDA and SCL			0.4	V
V <sub>IH</sub>	Input high threshold level	V <sub>pull_up</sub> =1.8V, SDA and SCL	1.3			V
I <sub>BIAS</sub>	Input bias current	V <sub>pull_up</sub> =1.8V, SDA and SCL			1	μA

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>THERMAL PROTECTION</b>						
T <sub>J_REG</sub>	Junction temperature regulation	Junction temperature rising		120		°C
T <sub>OTP</sub>	Overheating shutdown protection temperature	Junction temperature rising		150		°C
	Thermal hysteresis for T <sub>OTP</sub>	Junction temperature falling		20		°C
I <sub>NTC</sub>	NTC pin output current	CEB=0, NTC=3V	-1	0	1	μA
V <sub>COOL</sub>	NTC cool temp rising threshold	Percentage of VDD	62	64	66	%
	Hysteresis voltage			60		mV
V <sub>HOT</sub>	NTC hot temp falling threshold	Percentage of VDD	31	33	35	%
	Hysteresis voltage			70		mV
V <sub>HOT_PCB</sub>	NTC hot temp falling threshold for PCB OTP	Percentage of VDD	31	33	35	%
	Hysteresis voltage			70		mV
<b>SHIPPING MODE EXIT TIME</b>						
T <sub>EXIT_SHIPMODE</sub>	VBUS Plug in	REG0BH[0]=0	1.8	2	3.3	s
		REG0BH[0]=1	90	100	111	ms
	Put down INT PIN	REG22H[3]=0	1.8	2	3.3	s
		REG22H[3]=1	90	100	111	ms
<b>CLOCK FREQUENCY AND WATCHDOG TIMER</b>						
F <sub>CLK</sub>	Clock frequency			250		KHz
t <sub>WDT</sub>	Watchdog timer	REG05H[6:5]=11		160		s

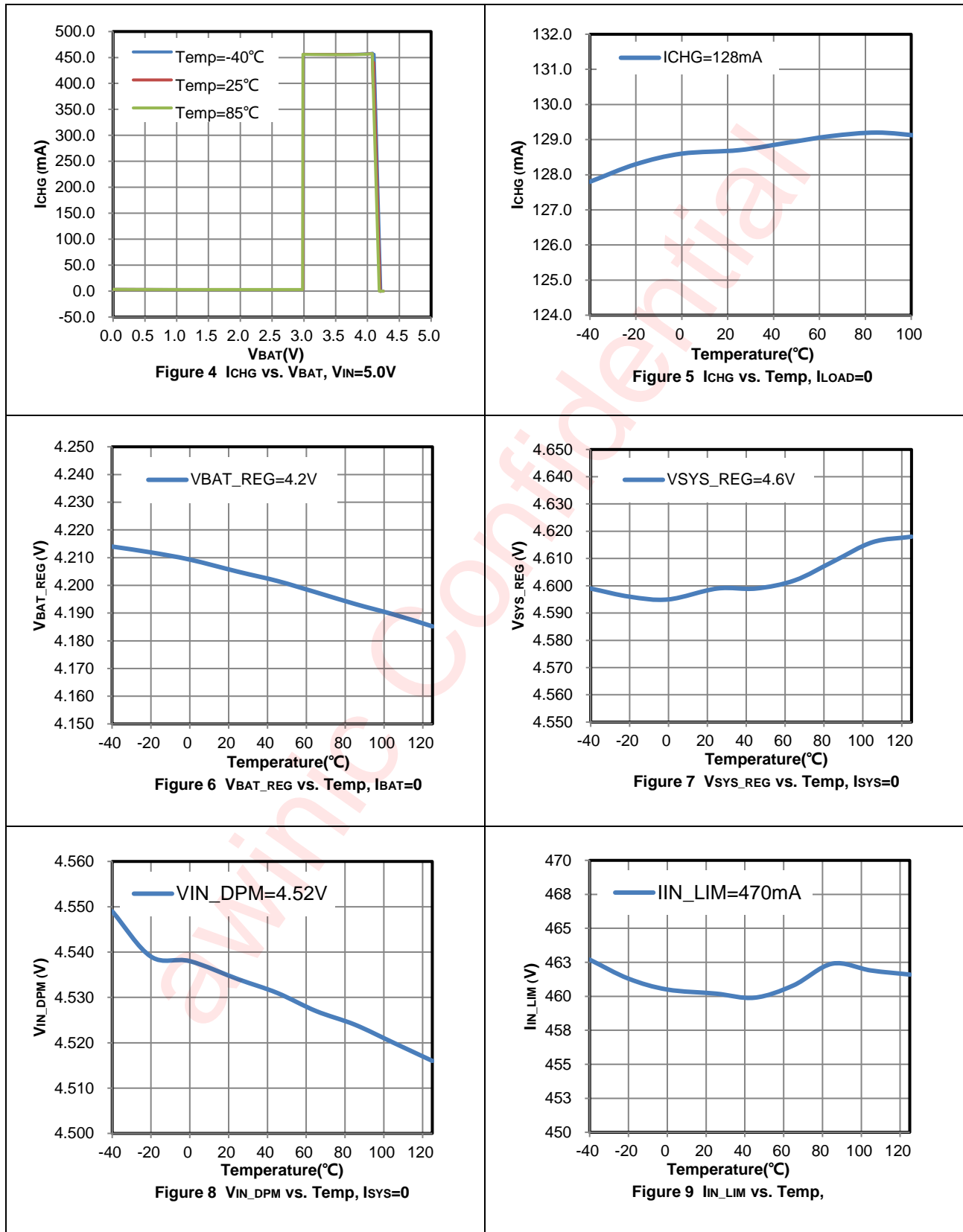
**Electrical Characteristics (Continued)** $V_{IN}=5V$ ,  $V_{BAT}=3.5V$ ,  $T_J=25^\circ C$  for typical values (unless otherwise noted)**I<sup>2</sup>C INTERFACE TIMING**

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
$F_{SCL}$	Interface Clock Frequency			400	kHz
$T_{DEGLITCH}$	Deglitch Time	SCL	83		ns
		SDA	115		ns
$t_{HD:STA}$	(Repeat-Start) Start Condition Hold Time	0.6			$\mu s$
$t_{LOW}$	Low Level Width of SCL	1.3			$\mu s$
$t_{HIGH}$	High Level Width of SCL	0.6			$\mu s$
$t_{SU:STA}$	(Repeat-Start) Start Condition Setup Time	0.6			$\mu s$
$t_{HD:DAT}$	Data Hold Time	0			$\mu s$
$t_{SU:DAT}$	Data Setup Time	0.1			$\mu s$
$t_R$	Rising Time of SDA and SCL			0.3	$\mu s$
$t_F$	Falling Time of SDA and SCL			0.3	$\mu s$
$t_{SU:STO}$	Stop Condition Setup Time	0.6			$\mu s$
$t_{BUF}$	Time Between Start and Stop Condition	1.3			$\mu s$

**Figure 3 I<sup>2</sup>C Interface Timing**

### Typical Characteristics

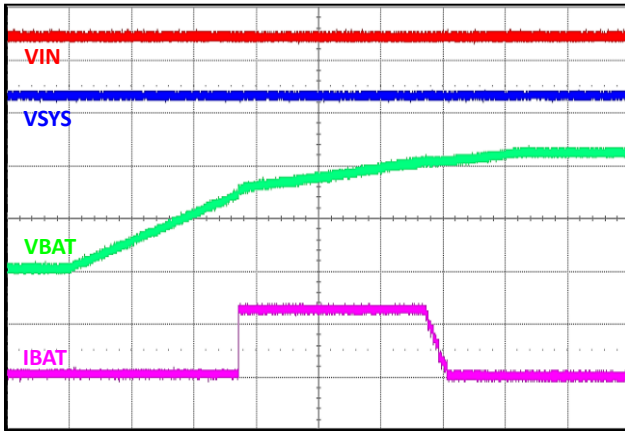
$V_{IN}=5V$ ,  $T_J=25^\circ C$ ,  $I_{IN\_LIM}=500mA$ ,  $I_{CHG}=128mA$ ,  $V_{IN\_DPM}=4.6V$ , unless other noted.



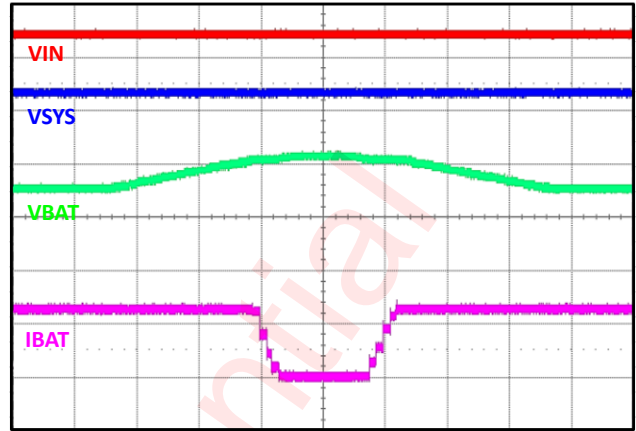
### Typical Characteristics

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C1 2V/ C2 2V/ C3 2V/ C4 100mA/



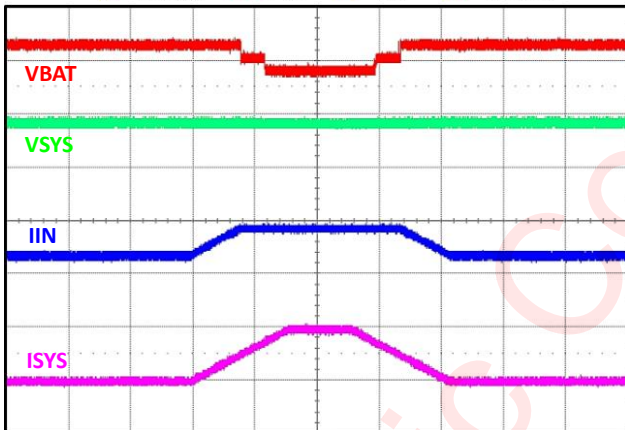
C1 2V/ C2 2V/ C3 2V/ C4 100mA/



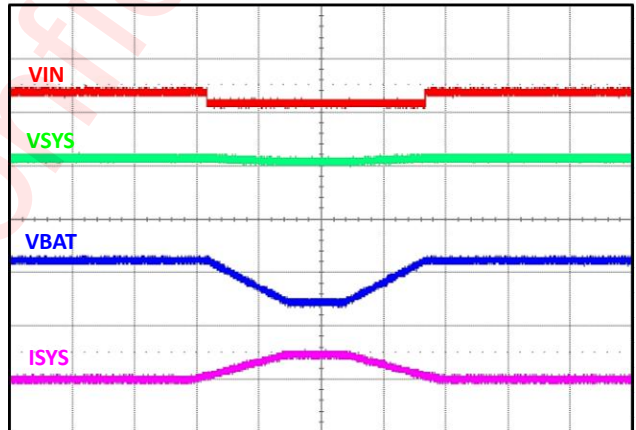
$I_{SYS}=0A$   
Battery Charge Curve

$I_{SYS}=0A$   
Auto-Recharge Curve

C1 500mA/ C2 2V/ C3 2V/ C4 500mA/



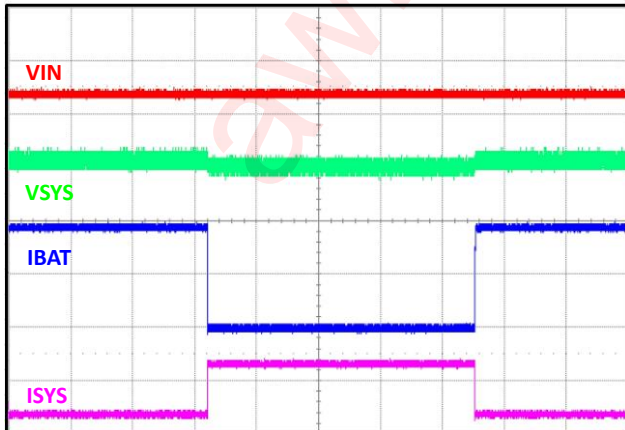
C1 500mA/ C2 1V/ C3 2V/ C4 1A/



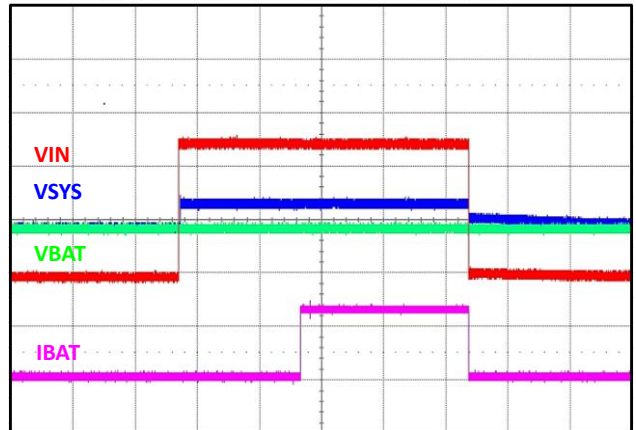
$V_{BAT}=3.7V$   
Input Current Limit-Based PPM

$V_{IN}=5V/200mA$ ,  $V_{BAT}=3.7V$   
Input Voltage Regulation-Based PPM

C1 500mA/ C2 1V/ C3 2V/ C4 1A/



C1 2V/ C2 2V/ C3 2V/ C4 100mA/



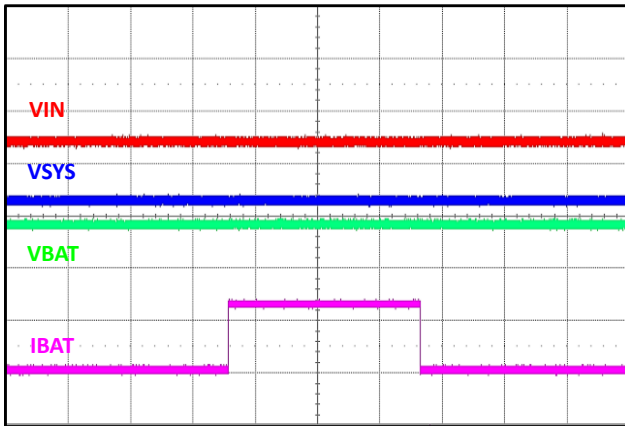
$V_{IN}=5V$ ,  $V_{BAT}=3.7V$ ,  $I_{CHG}=456mA$ ,  $I_{SYS}=0A\sim 1A$   
SYS Load Transient

$V_{BAT}=3.7V$ ,  $I_{SYS}=0A$   
Power On/Off

### Typical Characteristics (Continued)

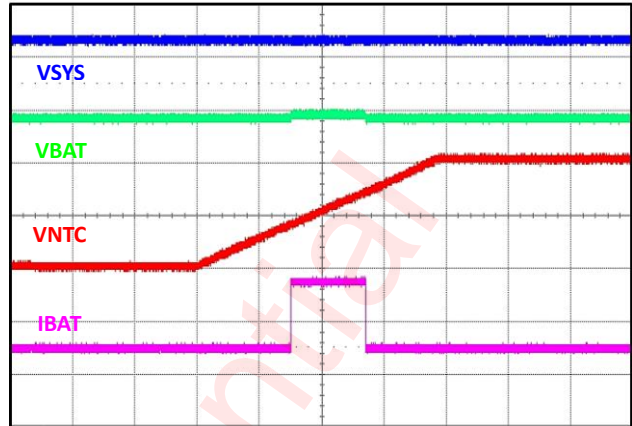
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C1 2V/ C2 2V/ C3 2V/ C4 100mA/



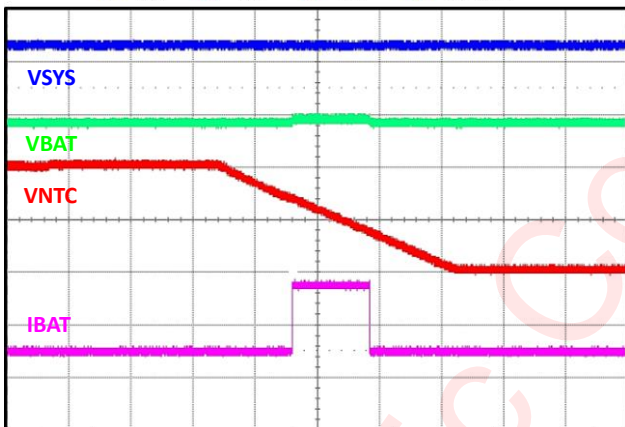
$V_{BAT}=3.7V$ ,  $I_{SYS}=0A$   
Charge Enable/Disable

C1 2V/ C2 2V/ C3 2V/ C4 100mA/



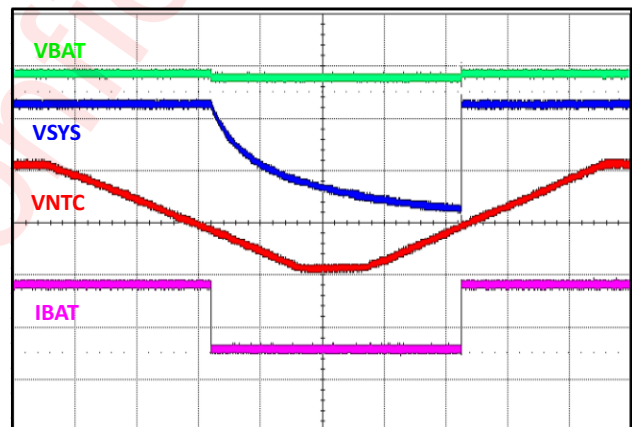
$V_{BAT}=3.7V$ ,  $I_{SYS}=0A$ , PCB\_OTP disabled  
NTC Rising

C1 2V/ C2 2V/ C3 2V/ C4 100mA/



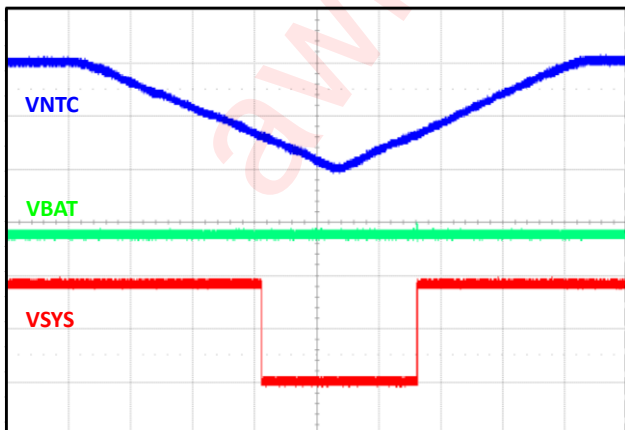
$V_{BAT}=3.7V$ ,  $I_{SYS}=0A$ , PCB\_OTP disabled  
NTC Falling

C1 2V/ C2 2V/ C3 2V/ C4 100mA/



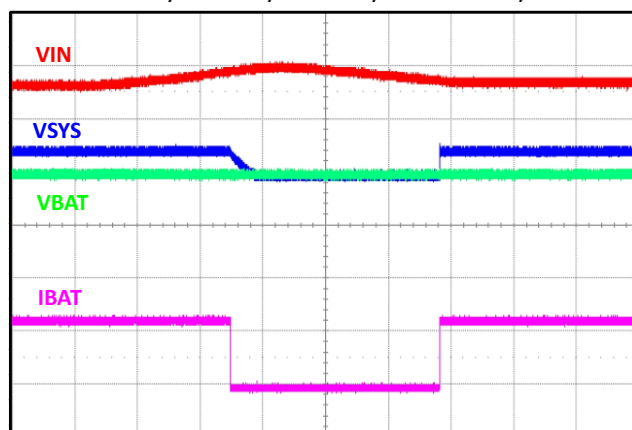
$V_{BAT}=3.7V$ ,  $I_{SYS}=0A$   
PCB\_OTP @Charge mode

C1 2V/ C2 1V/ C3 2V/



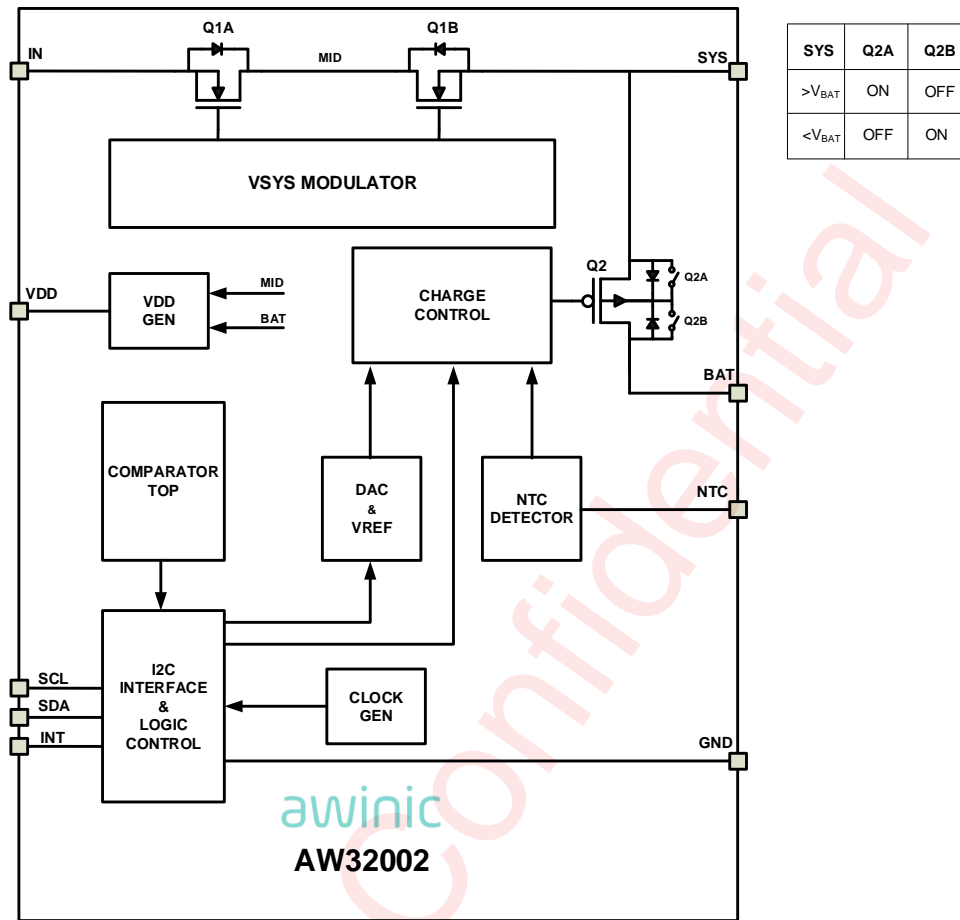
$V_{IN}=0V$ ,  $V_{BAT}=3.7V$   
PCB\_OTP @Discharge mode

C1 2V/ C2 2V/ C3 2V/ C4 100mA/



$V_{BAT}=3.7V$ ,  $I_{SYS}=0A$   
 $V_{IN}$  OVP Operation

**Functional Diagram**



**Figure 10 Functional Block Diagram**

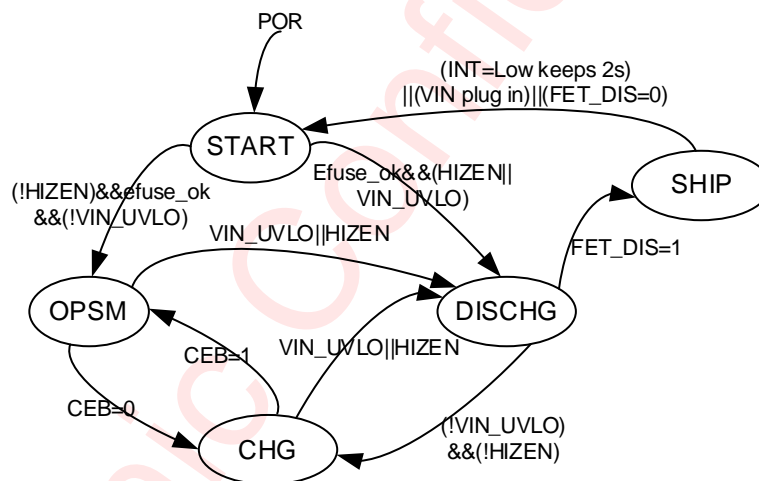
## Detailed Functional Description

The AW32002 is a highly integrated linear battery charger with a complete power path management function (PPMF). The full-charge process of AW32002 not only includes pre-charge, constant-current fast charge (CC) and constant voltage (CV) regulation, but also charge termination, auto-recharge, etc. The PPMF can manage the input source to power the system load and charge the battery simultaneously. The system load has a higher priority than the charge current. When the input power is limited by input current or voltage, the charge current will decrease automatically.

### Main Machine

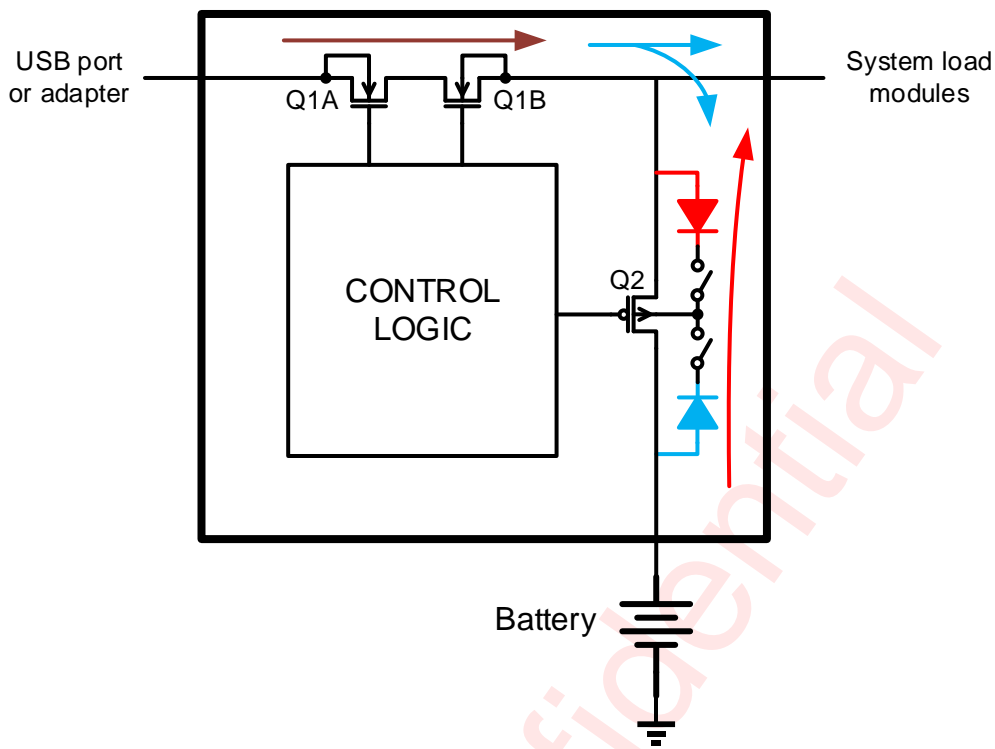
AW32002 includes: START, Battery Discharge Mode(DISCHG), Battery Charge Mode(CHG), Only Power System Mode(OPSM) and Shipping Mode(SHIP), Figure 11 is shown the main state machine conversion.

- (1) Battery Discharge Mode: Only Battery to SYS Path is enabled.
- (2) Battery Charge Mode: IN to SYS path and SYS to Battery path are enabled.
- (3) Only Power System Mode: Only IN to SYS Path is enabled.
- (4) Shipping Mode: All paths are disabled, AW32002 enters into low power consumption state.



**Figure 11 The main state machine conversion**

The AW32002 integrates an input reverse-block FET (Q1A), a LDO FET (Q1B) between IN and SYS, and a BATFET (Q2) between SYS and BAT. When VBUS plugs in and CEB=1, the device works in OPSM mode that only IN and SYS path is enabled, the system is powered by VBUS. If CEB=0, the charge function is enabled and Q2 turn on, the status switches to Battery Charge mode(CHG). When the system load demand is over the input power capacity, the PPMF of AW32002 will reduce the charging current or use power from the battery to satisfy the system load. The charge current is limited to maintain the system power supply with higher priority all the time. Figure 12 shows the PPMF structure of the AW32002, which is called Battery Supplement Mode too. Once the VBUS is unplugged, the BATFET Q2 is turn on fully to supply the system, and the charger enters into Battery Discharge Mode(DISCHG). Further, the device can turn off BATFET so that the system voltage is zero to minimize the battery leakage current. When the host set FET\_DIS=1, the charger can turn off BATFET Q2 and entries Shipping Mode(SHIP).

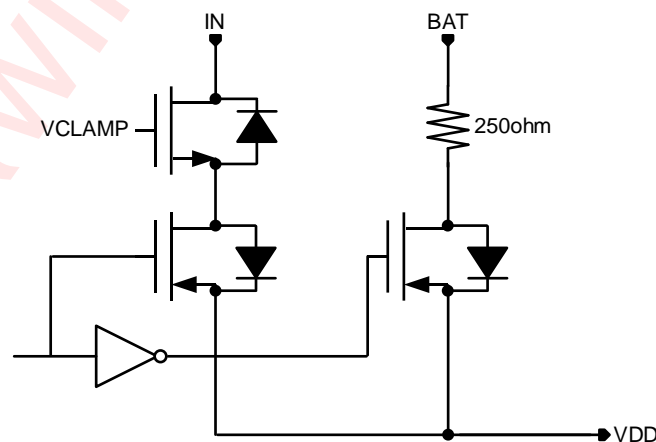


**Figure 12 Power Path management Structure**

In Battery Charge Mode, the Q2 works as a fully featured linear charger with pre-charge, fast charge, constant voltage charge, charge termination, auto-recharge, thermal protection, built-in timer control and NTC monitoring. The charge current can be programmed via the I<sup>2</sup>C interface. When the chip's temperature exceeds the thermal regulation threshold (120°C default), the IC controls the charge current to reduce its temperature.

## Power Supply

The AW32002 chooses the higher voltage of either BAT or IN to power VDD and the internal bias circuit, showed as Figure 13. When BAT or IN voltage rises above its respective power on reset (POR) threshold, the internal control circuit will wake up and the I<sup>2</sup>C interface will be ready for communication with all of registers reset to default value. These registers can be controlled by the host.



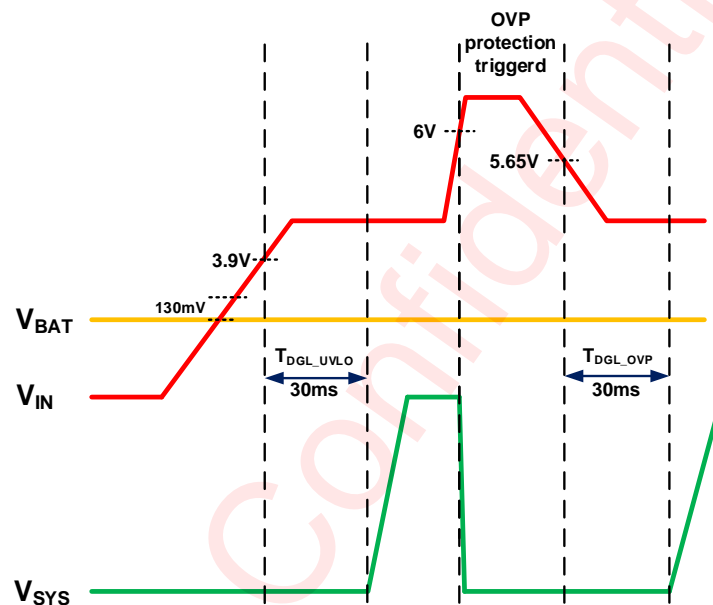
**Figure 13 The inner power supply sources selection circuit for VDD**

**VIN OVP, VIN UVLO and VIN GOOD**

The AW32002 has an input UVLO and over-voltage protection (OVP) threshold. The Q1 is turned off immediately when the input voltage is out of its operating range.

The input over-voltage protection is integrated to prevent the device and other components from damage of the high input voltage (Voltage from VIN to GND). If the voltage at VIN pin exceeds  $V_{IN\_OVP}$  threshold(6V typical), the chip will turn off Q1. When  $V_{IN}$  drops lower than the input overvoltage exit threshold (5.65V typical) and continues to exceed  $T_{DGL\_OVP}$ (30ms typical), Q1 will be turned on again.

When  $V_{IN}$  falls below  $V_{UVLO}$ , the Q1 is also turned off and the input to system loop controller is shut down. Once  $V_{IN}$  rises above  $V_{UVLO}+300mV$  and continues to exceed  $T_{DGL\_UVLO}$ (30ms typical), the Q1 is turned on and relative circuits start working.



**Figure 14 Input Power Detection Operation**

Either  $V_{IN}$  OVP or  $V_{IN}$  UVLO had happened, the device send out a  $256\mu s$  low-state interrupt pulse from INT port, indicated a power fail status as  $REG08H[1]=0$  and a fault status as  $REG09H[5]=1$ , which are read clear.

The VIN GOOD status not only means that  $V_{IN}$  is between  $V_{IN\_UVLO}$  and  $V_{IN\_OVP}$ , but also .includes that the VIN voltage increase is higher than  $V_{BAT}+170mV$ (130mV typical), and higher than  $V_{SYS}+75mV$ (50mV typical). The all conditions have satisfied, and enter VIN GOOD. VIN voltage reduction meets  $V_{IN}<V_{BAT}+60mV$  or  $V_{IN}<V_{SYS}-50mV$ , exiting VIN GOOD.

**Only Power System Mode**

The device meets VIN GOOD,  $EN\_HIZ=0$ ( $REG01H[4]=0$ ) and  $CEB=1$ ( $REG01H[3]=1$ ), and firstly enter Only Power System Mode(OPSM) which just turns on Q1A and Q1B, and supplies power the down-stream system by VBUS. If the device is configured  $CEB=0$ ( $REG01H[3]=0$ ), the main state machine switches to Charge Mode from the Only Power System Mode.

**Charge Mode**

When AW32002 operation in Charge Mode, the DPM, PPMF, Battery Supplement and other functions are available. These functions are useful in some application.

### Battery Regulation Voltage

The battery voltage of constant voltage regulation state is  $V_{BAT\_REG}$ . When  $V_{BAT\_REG} = 4.2V$ , the accuracy is  $\pm 0.5\%$  in the range of  $0^{\circ}C$  to  $+50^{\circ}C$  ambient temperature.

### Input Current-and Input Voltage-Based Power Regulation

The AW32002 has an input current limit regulation to meet the input source's (typically USB) maximum current limit specification. The function is realized by monitoring the input current continuously. If the rating of input source is lower than the preset input current limit, the input current limitation works to protect the input source from being overloaded. The total input current limit value can be set by the register IIN\_LIM (REG00H[3:0]), and the function can prevent the input source from being over-loaded.

Otherwise, when the load is over the input power capacity, the input voltage also can be regulated to  $V_{IN\_DPM}$  for the input voltage-based DPM regulation.  $V_{IN\_DPM}$  can be set via the register VIN\_DPM (REG00H[7:4]), and the  $V_{IN\_DPM}$  should be at least 250mV higher than  $V_{BAT\_REG}$  to ensure the stable operation of the regulator. The register DIS\_VINLOOP=1 (REG07H[6]=1) can be set to disable the input voltage limit function.

Either the input voltage or input current limit is reached, the total input power is limited by regulating the Q1B FET between IN and SYS. As a result, the system voltage drops. When the system voltage decrease to a **minimum value** of  $V_{SYS\_REG} - 135mV$  and  $V_{IN} - 345mV$ , the charge current is reduced to prevent the system voltage from dropping further.

### Power Path Management Function (PPMF)

The AW32002 can decouple the system from the battery by employs a PPMF with the Q2, which allows the device to control Q2 between the system and the battery separately. The system has high priority to start up by regulating the integrated Q1B even the battery is in a deeply discharged or missing state. The function of Q1A, Q1B and Q2 can be controlled by the I<sup>2</sup>C as shown in table 1.

Table 1: FET Control via I<sup>2</sup>C

FET On/Off Changed by Control	HI-Z Mode and Charge Control	
	Set EN_HIZ = 1	Set CEB = 1
Q1A and Q1B	OFF	x
Q2(Charge Mode)	x	OFF
Q2(Battery Discharge Mode)	x	x

**NOTE:** x=Don't care.

For the system voltage control, when the input voltage is lower than  $V_{SYS\_REG}$ , the Q1A and Q1B are fully on with the input current limit. When the input voltage is higher than  $V_{SYS\_REG}$ , the system voltage is regulated to  $V_{SYS\_REG}$ . The  $V_{SYS\_REG}$  can be programmed through REG07H[3:0].

### Battery Supplement Mode

When DPM occurs, the charge current is reduced to keep the input current or input voltage in regulation. If the charge current has already reduced to zero and the input source is still overloaded, the system voltage begins decreasing. If the system voltage drops to 30mV below the battery voltage, the AW32002 will enters battery supplement mode, and the ideal diode is enabled. If  $I_{DSCHG}$  (supplement current) \*  $R_{ON\_BATT}$  is lower than 30mV, the Q2 is regulated to keep  $V_{BAT} - V_{SYS}$  at 30mV. If this regulation cannot maintain 30mV voltage drop due to heavy load from SYS, the Q2 will fully turn on to maintain the ideal forward voltage. When the system load decreases, the system voltage starts to increase. The ideal diode mode is disabled, when  $V_{SYS}$  is higher than  $V_{BAT} + 20mV$ . Figure 15 shows the DPM and battery supplement mode operation profile.

When  $V_{IN}$  is not available, the AW32002 operates in discharge mode. During in discharge mode, the Q2 is fully on to reduce power loss.

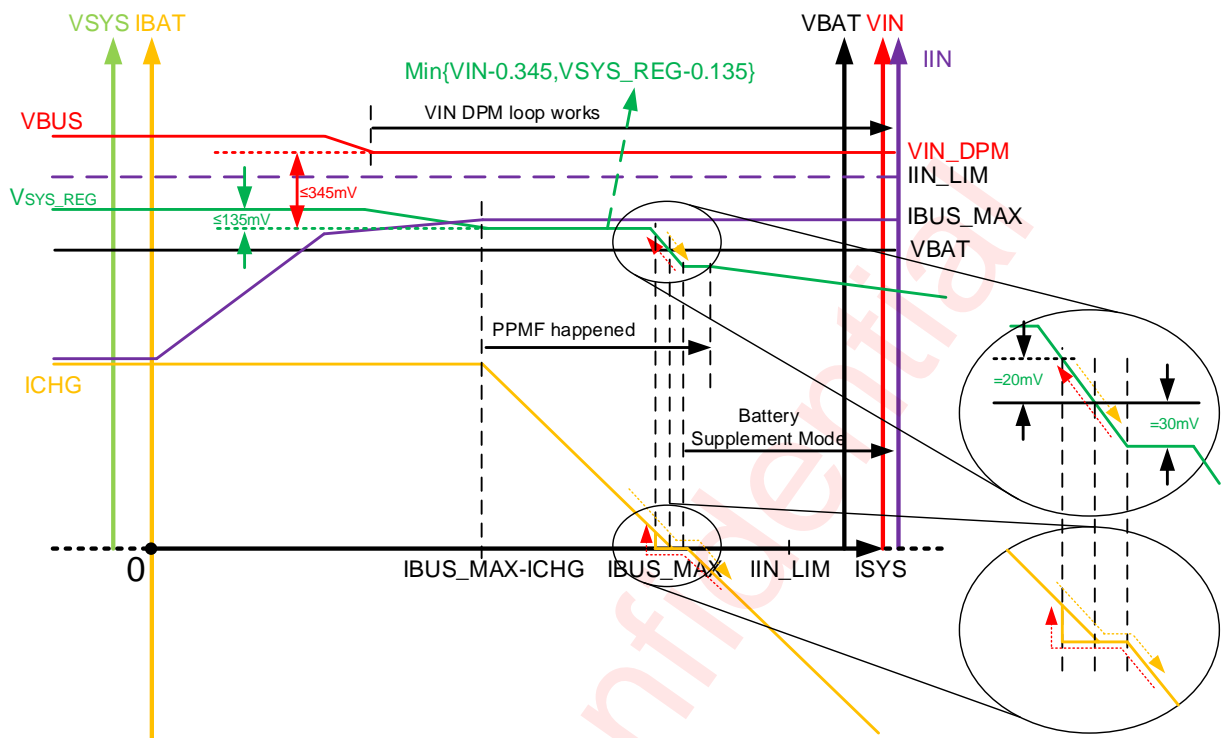


Figure 15 DPM and Battery Supplement Operation Profile (Bad adaptor inserted)

**NOTE:** IBUS\_MAX is the maximum output current of the input source.

### Battery Charge Profile

The AW32002 has three main charging processes: pre-charge, fast constant current charge(CC), and fast constant voltage charge(CV):

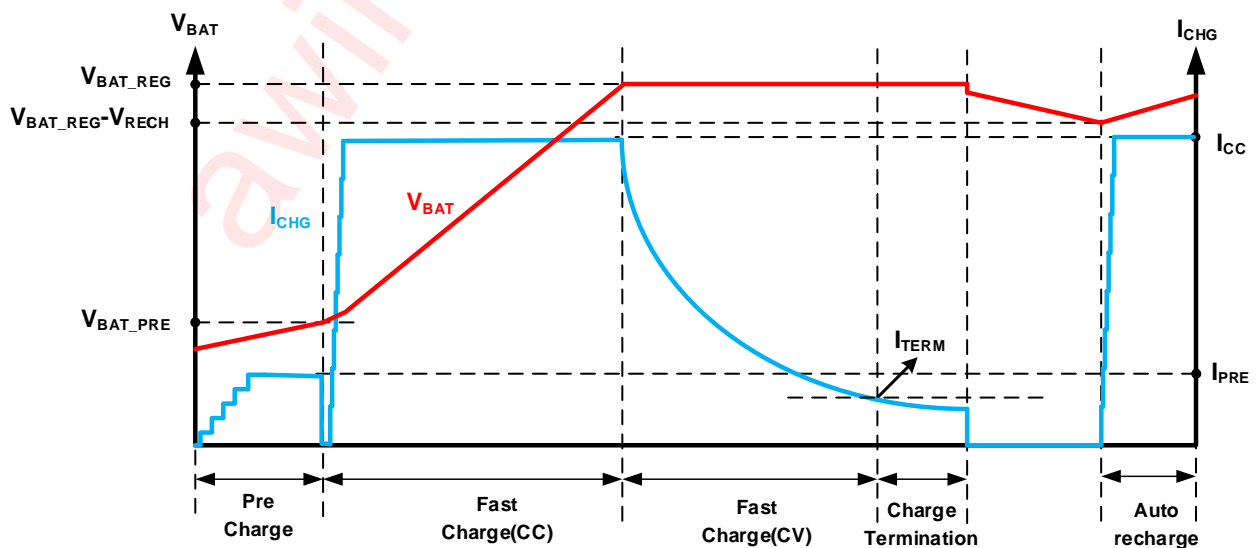


Figure 16 Battery Charge Profile

- Pre-charge: In the pre-charge process, the IC charges the deeply depleted battery safely with small current until the battery voltage rise to the pre-charge threshold ( $V_{BAT\_PRE}$ ), and then the chip enters the fast-charge process. If the  $V_{BAT}$  is not increasing to exceed than  $V_{BAT\_PRE}$  before the pre-charge timer expires (1 hour), the charge cycle stops, and a corresponding timeout fault signal is asserted. The register REG03H[3:0] can be set the current of pre-charge.
- Fast constant current charge: When  $V_{BAT}$  exceeds  $V_{BAT\_PRE}$ , the AW32002 enters the fast constant charge process. The REG02H[5:0] can be set to change the fast-charge current .
- Fast constant voltage charge: The charge mode changes from CC mode to CV mode when the  $V_{BAT}$  rises to the battery-full voltage ( $V_{BAT\_REG}$ ) set via REG04H[7:2]. At the same time, the charge current starts decreasing in CV charge process.

Due to multiple loop regulations, such as dynamic power management (DPM) regulation (input voltage, input current) or thermal regulation, the actual charge current may be less than the setting value.

When the charge current is smaller than termination current threshold  $I_{TERM}$  for 3.2s in CV process, the charge cycle will be completed, and the charge status is updated to charge done. The register REG03H[3:0] can set the termination charge current threshold  $I_{TERM}$ . The termination function can be disabled via  $EN\_TERM=0$  (REG05H[4]=0). Meanwhile, the register bit  $TERM\_TMR$  (REG05H[0]) is able to control whether the charge process continue or not when the termination conditions are met. The termination function is shown as table 2.

Table 2: Termination Function Selection Table

EN_TERM	TERM_TMR	After Termination Condition is Met	
		Operation	Charge Status
0	x	Keep CV Charge	Charge
1	0	Charge done	Charge done
1	1	Keep CV Charge	Charge

**Note:** x=Don't care.

A new charge cycle starts when any of the following conditions are valid:

- Auto-recharge kicks in.
- Battery charging is enabled via the I<sup>2</sup>C.
- The input power is recycled .

Under the following conditions:

- No safety timer fault.
- No thermistor fault at NTC.
- BFET is not forced off.
- No battery over-voltage event.

### Automatic Recharge

After the charge process is completed and charge cycle is terminated, the system's consumption or battery self-discharge may cause the battery voltage to decrease. When the battery voltage falls below the recharge threshold and  $V_{IN}$  is still in the operating range, another new charging cycle will start automatically. The recharge threshold(below  $V_{BAT\_REG}$ )  $V_{RECH}$  can be configured to 100mV or 200mV(default) via REG04H[0].

## Battery Discharge Mode

In Battery discharge mode, The device has low quiescent current and low on-resistance of Q2 to help the battery working for a longer time. Once the discharge current exceeds the over discharge current threshold, the over discharge current protection works and ensures the IC work safely in different applications.

### Battery Discharge Function

When the input source is absent and battery is connected to chip with the VBAT above  $V_{BAT\_UVLO}$  threshold, the Q2 is fully on. During discharge mode, the 90mΩ Q2 can minimizes conduction loss.

### Battery Disconnection Function

In some applications where the battery is not removable, it is essential to allow the system power to be reset in some applications or disconnect the battery from the system for shipping mode. The AW32002 provides both system reset function and shipping mode for different applications.

The INT pin can be used to cut off the path from the battery to the system under certain condition to reset the system manually. The battery is disconnected from the system, when the logic of INT is set low for longer than  $t_{RST\_DGL}$  (which can be programmed by REG01H[7:6]). After a delay time of  $t_{RST\_DUR}$  (REG01H[5]), the Q2 is turned on automatically, and the system is powered by the battery again. The  $t_{RST\_DUR}$  can be programmed by REG01H[5]. During the off period, the INT pin is not limited to be high or low. Please notes that the  $t_{RST\_DGL}$  counter is triggered by the falling edge of INT.

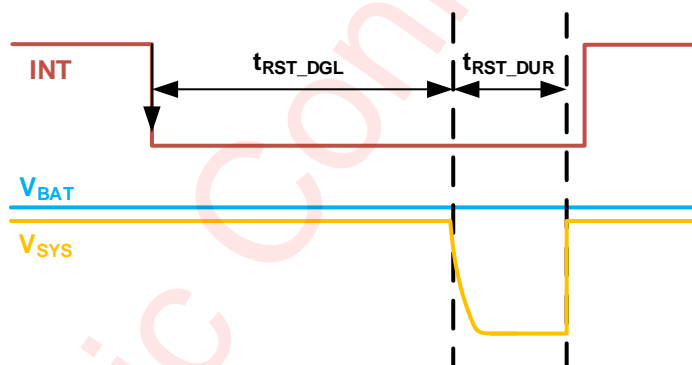


Figure 17 System Reset Function Operation Timing Diagram

## Shipping Mode

The register bit FET\_DIS (REG06H[5]) can be used to control the battery disconnection too. If the input source is absent, once setting FET\_DIS=1, the AW32002 enters shipping mode after a delay time(default 1s). The delay time can be programmed by EN\_SHIPPING\_DGL(REG09H[7:6]). If the input source is present when FET\_DIS is written to 1, chip will turn to shipping mode after 2s deglitch time with input voltage smaller than  $V_{IN\_UVLO}$  threshold. Plug in the input adapter or pull the INT pin down for 2s or 100ms to wake the AW32002 up from shipping mode. The waking time can be configured in EN\_SHIPMD\_0P1S (REG0BH[0]) and INT100MS (REG22H[3]).

If INT PIN is shorted to ground or left floating before entering Shipping Mode, DIS\_SHIPINT (REG0CH[2]) must be written to 1 to avoid bad Shipping Mode operation. In this case, the only method of exiting shipping mode is plugging in the input adapter.

Table 3: Shipping Mode Control

FET On/Off Changed by Control	Enter Shipping Mode	Exit Shipping Mode	
	Set FET_DIS to 1	INT H to L for 2s	Vin Plug-In
Q1	x	x	On
Q2	Off(1s later)	On	On(2s later)

Note: x=Don't care.

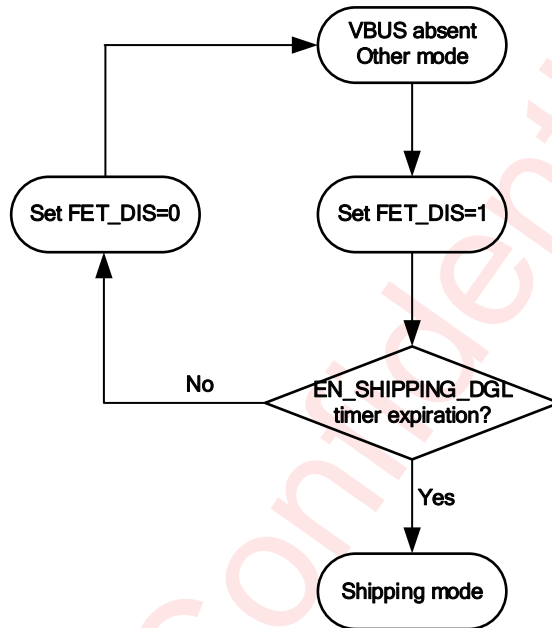


Figure 18 Enter Shipping Mode Timing Diagram(VBUS absent)

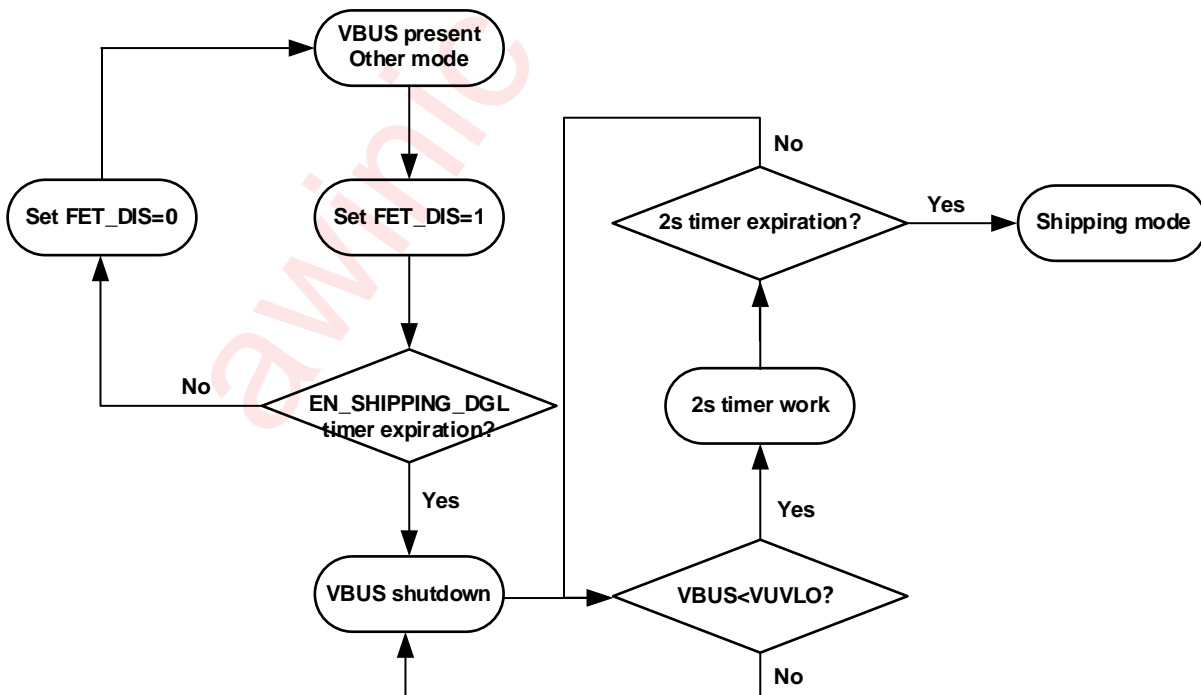


Figure 19 Enter Shipping Mode Timing Diagram(VBUS present)

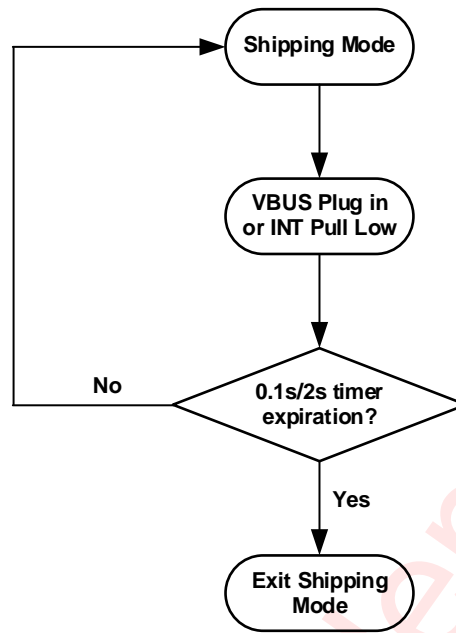


Figure 20 Exit Shipping Mode Timing Diagram

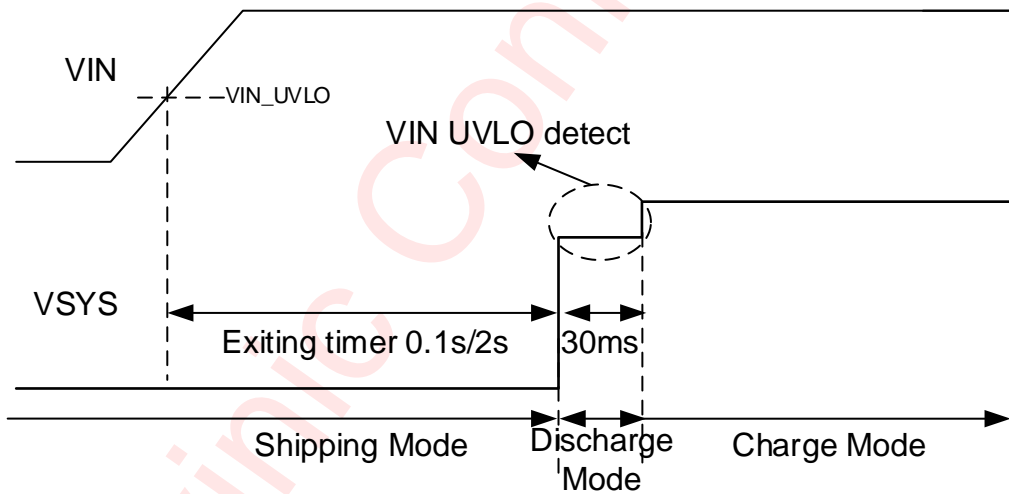


Figure 21 Recovery charging From Shipping Mode Operation Timing Diagram(VBUS Plug-In)

## Protection Operation

The AW32002 has input OVP, UVLO, battery OVP and other functions to protect its normal operation. Additionally, NTC function is integrated to prevent battery from high temperature danger. The following table 4 is all fault functions summary table.

Table 4: All fault functions summary table

Status	Operation Mode	Brief Function Description	Interrupt	Action
VIN GOOD	Charge, OPSPM	$V_{IN}$ rises above $V_{BAT}+170mV$ and $V_{SYS}+75mV$ , the device enters into VIN Good, $V_{IN}$ falls down $V_{BAT}+60mV$ or $V_{SYS}-50mV$ , exits VIN GOOD. Entry and exit require 2ms to confirm.	Yes	Turn on Q1A and Q1B.
VIN UVLO	Charge, OPSPM	$V_{IN}$ falls down 3.3V, the device enters VIN UVLO immediately. $V_{IN}$ rises above 3.6V and keeps 30ms, the device exits.	Yes	Turn off Q1A and Q1B.
VIN OVP	Charge, OPSPM	$V_{IN}$ rises above 6V, the device enters into VIN OVP immediately, $V_{IN}$ falls down about 5.65V, exits VIN OVP. Exit requires 30ms to confirm.	Yes	Quickly turn off Q1B in 100ns.
VBAT OVP	Charge	After $V_{BAT}$ rises above $V_{BAT\_REG}+130mV$ about 128 $\mu s$ , the device enters into VBAT OVP. Once $V_{BAT}$ falls down $V_{BAT\_REG}+50mV$ about 2ms, exits VBAT OVP.	Yes	Turn off Q2.
VBAT UVLO	Discharge, OPSPM	When $V_{BAT}$ rises above $V_{BAT\_UVLO}+190mV$ about 31ms (programmable 128 $\mu s$ ), the device exits into $V_{BAT\_UVLO}$ . Once $V_{BAT}$ falls down $V_{BAT\_UVLO}$ (programmable), enters $V_{BAT\_UVLO}$ immediately.	No	Turn off Q2.
OTP	Charge, OPSPM, Discharge	When the junction temperature exceeds 150°C, IC shuts down. When the junction temperature falls below the thermal recovery temperature, approximately 130°C, the device restarts by using the soft-start sequence.	Yes	Turn off Q1B and Q2.
PCB OTP	Charge, OPSPM, Discharge	PCB_OTP function is default settings. $V_{NTC}$ falls down $V_{DD}\times 33\%$ , PCB OTP is valid; Once $V_{NTC}$ rises up $V_{DD}\times 33\%+70mV$ for 31ms, the device exits PCB OTP.	Yes	Turn off Q1B and Q2.
NTC HOT	Charge	NTC HOT function is configured. $V_{NTC}$ falls down $V_{DD}\times 33\%$ , the device judges battery hot, and reports NTC HOT; Once $V_{NTC}$ rises up $V_{DD}\times 33\%+70mV$ for 31ms, the device exits NTC HOT.	Yes	Turn off Q2.
NTC COOL	Charge	NTC COOL function is configured. $V_{NTC}$ rises up $V_{DD}\times 64\%$ , the device judges battery cool, and reports NTC COOL; Once $V_{NTC}$ falls down $V_{DD}\times 64\%-60mV$ for 31ms, the device exits NTC COOL.	Yes	Turn off Q2.

VSYS SCP	Charge, OPSP, Discharge	When the events including $I_{SYS} > I_{OCP\_INSYS}(2A)$ , $I_{SYS} > I_{OCP\_BATSYS}(3.7A)$ , $I_{IN\_LIM} < I_{SYS} < I_{OCP\_INSYS}$ for 60us, and $I_{DSCHG} < I_{SYS} < I_{OCP\_BATSYS}$ for 60us happen during $V_{SYS}$ launch and $V_{SYS} < 0.7V$ , or during working normally and $V_{SYS} < 1.5V$ , the device triggers $V_{SYS}$ short protection immediately and work in Hiccup Mode. Turn off Q1 and Q2, and start up again after 1ms later.	No	Hiccup Mode. Turn off Q1 and Q2, and start up again after 1ms later
VBAT ODCP	Discharge, Supplement Mode	Over-discharge current protection. Once the $I_{BAT}$ exceeds the programmable discharge current limit $I_{DSCHG}$ (2A default) for 60us. The AW32002 enters hiccup mode. In addition, if the discharge current goes high and reaches the internal fixed peak current limit (about 3.7A), the Q2 turns off and begins hiccup mode immediately.	No	Q2 turns off
Watch Dog fault	Charge, OPSP, Discharge	When the watchdog timer expires, both the Q1 and Q2 are turned off, and most registers return to the default value, sent a watch dog fault interrupt to system.	Yes	Turn off Q1B and Q2. Reset CEB to 0.
Safety time fault	Pre Charge, Fast Charge	Pre-charge for more than 1 hour (Configurable), or faster charge for more than 5 hours (Configurable), entry to safety time fault.	Yes	Turn off Q1B and Q2. Reset CEB to 0.

### Battery OVP(VBAT OVP)

The AW32002 has battery over-voltage protection (VBAT OVP) function (about 130mV higher than  $V_{BAT\_REG}$ ). When the battery OVP event occurs, AW32002 will stop the current charging cycle immediately and asserts a fault.

### Negative Temperature Coefficient (NTC) Temperature Sensor

The AW32002 is able to use NTC to sense the battery temperature. By monitoring the thermistor (usually available in the battery pack), the battery is guaranteed to operate in safe environment.

The NTC function demands appropriately valued resistors connecting from VDD to NTC to ground. At the same time, connect a thermistor from the NTC pin to ground. The NTC voltage is determined by the resistor divider and thermistor, and the divide ratio depends on the temperature of thermistor. The upper and lower bound of NTC voltage is pre-determined in AW32002.

In the AW32002, PCB\_OTP function is default settings. The I<sup>2</sup>C can change the NTC and PCB\_OTP functions (see Table 5).

Table 5: NTC Function Selection Table

I <sup>2</sup> C Control		Function
EN_NTC	DIS_PCB_OTP	
0	x	Disable
1	1	NTC(resistor-divided)
1	0	PCB_OTP

**NOTE: x=Don't care**

When PCB\_OTP is selected and the NTC voltage is lower than the NTC hot threshold, both the Q2 and Q1 are turned off. The NTC\_FAULT status is set (REG09H[1]) to 1 to show the PCB\_OTP fault. The IC Operation resumes, when the NTC voltage returns to safe range.

The NTC function works only in charge mode. Once the temperature is outside of the safe operating range, the IC stops charging state and report it on the status bits. When the temperature comes back to the safe range, the charge process resumes automatically.

***Thermal Regulation and Thermal Shutdown***

The internal junction temperature is monitored continuously to avoid overheating the chip and maximize power delivery. When the internal junction temperature reaches the preset limit  $T_{J\_REG}$  (120°C default), the charge current starts reducing to prevent dangerous high power dissipation. The IC can work in different thermal requirements applications, because it has multiple thermal regulation thresholds from 60°C to 120°C. register REG07H[5:4] can set The junction temperature regulation threshold.

The device has a built-in temperature sensor which monitors the internal junction temperature. When the junction temperature exceeds 150°C, the Q1 and Q2 will turn off. When the junction temperature falls below the thermal recovery temperature, approximately 130°C, the device reworks.

## System Short-Circuit Protection(VSYS SCP)

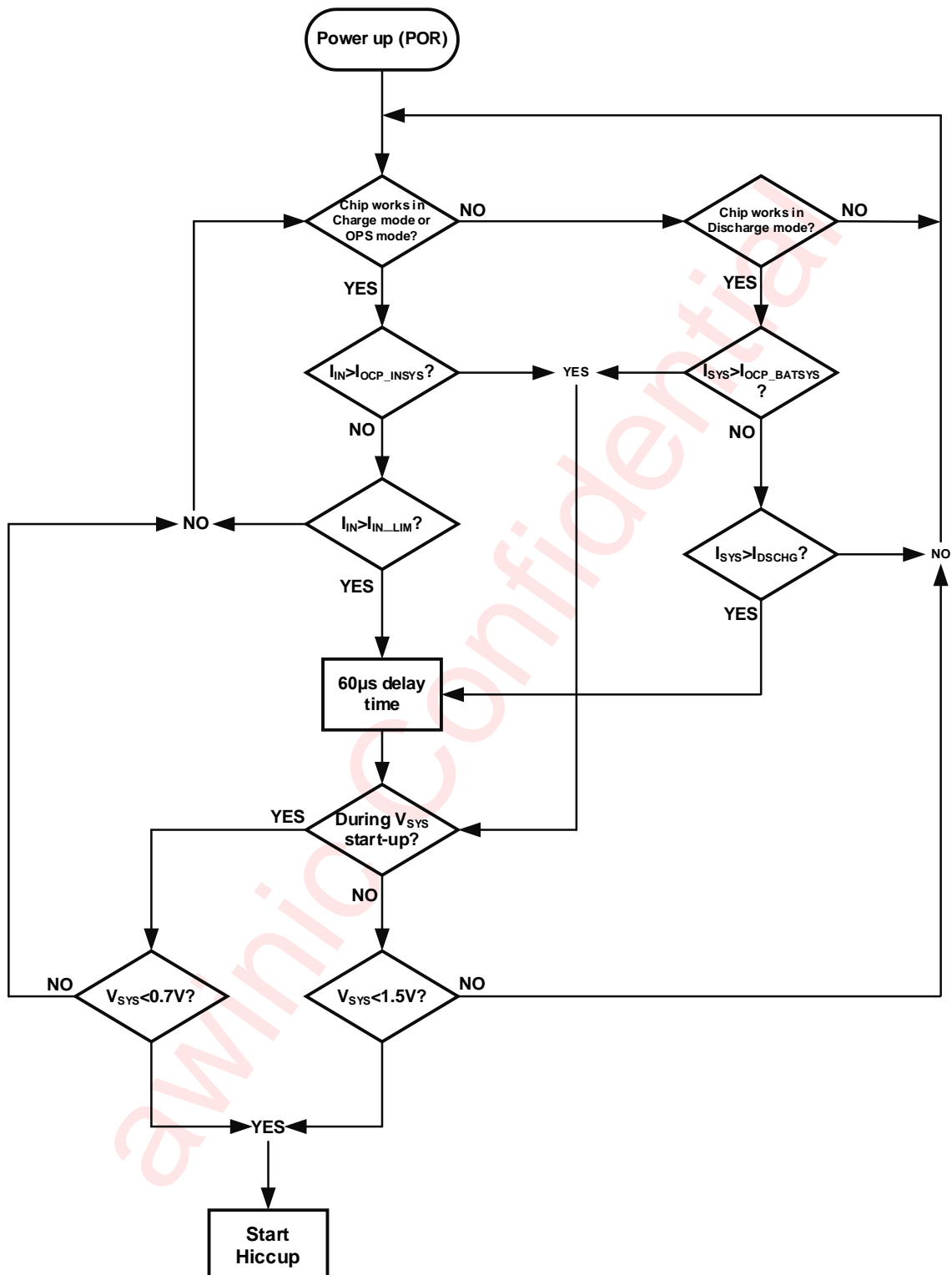


Figure 22 Short Circuit Hiccup Protection Flow Chart

The AW32002 has short-circuit protection (SCP) function in both the IN to SYS path and the BAT to SYS path. The IC monitor the system voltage continuously. If  $V_{SYS}$  is lower than 1.5V, The SCP is active, and  $I_{DSCHG}$  decreases to half of the original value. For the IN to SYS path, once  $I_{IN}$  is over the 2A protection threshold  $I_{OCP\_INSYS}$ , both the Q1 and Q2 are turned off immediately, and the AW32002 enters hiccup mode. When the

setting input current limit  $I_{IN\_LIM}$  is reached,  $I_{IN}$  is regulated at  $I_{IN\_LIM}$ . After a  $60\mu s$  delay, the hiccup mode starts, and the hiccup mode interval is 1ms. For the BAT to SYS path, once  $I_{BAT}$  is over the 3.7A protection threshold  $I_{OCP\_BATSYS}$ , both the Q1 and Q2 are turned off immediately, and the AW32002 enters hiccup mode. When the battery discharge current limit threshold  $I_{DSCHG}$  is reached, hiccup mode starts after a  $60\mu s$  delay, and the hiccup mode interval is 1ms.

Particularly, when system short-circuit occurs in both the input and battery, the both paths protection mechanism works together. The faster path dominates the hiccup operation.

### Over-Discharge Current Protection

In discharge mode and supplement mode, the AW32002 is designed to have an over-discharge current protection. Once the  $I_{BAT}$  exceeds the programmable discharge current limit (2A default), the Q2 turns off after a  $60\mu s$  delay. At the same time, the AW32002 enters hiccup mode as part of the over-current protection (OCP). The discharge current can be programmed to maximal 3.2A through the I<sup>2</sup>C. In addition, if the discharge current goes high and reaches the internal fixed peak current limit (about 3.7A), the Q2 turns off and begins hiccup mode immediately.

### Safety timer

Because the abnormal battery conditions, the AW32002 designed a pre-charge and fast-charge safety timer to prevent an extra-long time charging cycle. The pre-charge safety timer is 1hour, and the fast-charge safety timer can be programmed through the I<sup>2</sup>C. Once the battery enters fast-charge mode, The fast charge safety timer starts. The safety timer can be disabled via the I<sup>2</sup>C. When charger works in VIN DPM or Temp regulation state, the charge current will decrease. In order to charge as full as possible, the register bit TMR2X\_EN(REG06H[6]) could be set 1, which enable the timer slows down, the left safety time is double. If VIN DPM or Temp regulation state exit, or TMR2X\_EN=0, the timer recovery normal.

The following actions can restart the safety timer:

- Write REG05H[3] from 0 to 1 (safety timer enable).
- Write REG01H[3] from 1 to 0 (charge enable).
- Write REG02H[7] from 0 to 1 (software reset).
- A new charge cycle is kicked in.

### Interrupt to host (INT)

The AW32002 can output a  $256\mu s$  low-state INT pulse via INT to notify the system of the operation. All of the below events can trigger an INT output:

- Charge completed
- Good input source detected
- Charging status change
- UVLO or input over-voltage protection
- Any fault in REG09H and REG08H (input fault, watchdog timer fault, safety timer fault, thermal fault, battery OVP fault, NTC fault)

When a fault occurs, an INT pulse is send out and latches the fault state in REG09H and REG08H. After the AW32002 exits the fault state, the fault bit is reset to 0 after the host reads faults registers. The NTC fault bit constantly reports the current thermistor conditions without latches. The INT signal can be masked when the corresponding control bit is set in REG06H[4:0]. When an INT condition is masked, this means that the INT pin signal (and register bit) will not trigger when the corresponding condition occurs. Masking INT pulses is useful when writing software code to avoid unnecessary interruptions due to these events.

## Host Mode and Default Mode

The AW32002 is a host-controlled device. After the power-on reset, the AW32002 starts up in a default mode or watchdog timer expiration state. All registers are in their default settings.

In both charge and discharge mode, once the watchdog timer run out, both the Q1 and Q2 are turned off, and most registers return to the default value (refer to the I<sup>2</sup>C Register Map section). The Q1 and Q2 are turn on again automatically after  $t_{RST\_DUR}$ , which can be programmed by REG01H[5]. Also the watchdog timer can be turned off in discharge mode by setting REG05H[7]=0. If the watchdog timer (REG05H[6:5]) is not disabled, the host must reset the watchdog timer regularly by writing 1 to REG02H[6] before the watchdog timer expires to keep the device in host mode. When the watchdog timer expires, the AW32002 goes back to default mode. And any writing to the AW32002 will switch it to host mode. The watchdog timer limit can also be programmed or disabled by the host control.

In charge mode and OPSM, the watchdog timer is valid by default. In discharge mode, the watchdog timer is disable by default, and can be turned on by setting REG05H[7]=1. When the REG05H[6:5] is set to 00, the watchdog timer is disabled under both charge mode and discharge mode regardless of the status of REG05H[7]. Operation mode can be switched to default mode when one of the following conditions are valid:

- Register REG02H[7] is reset.
- Refresh input without battery.
- Re-insert battery with no VIN.

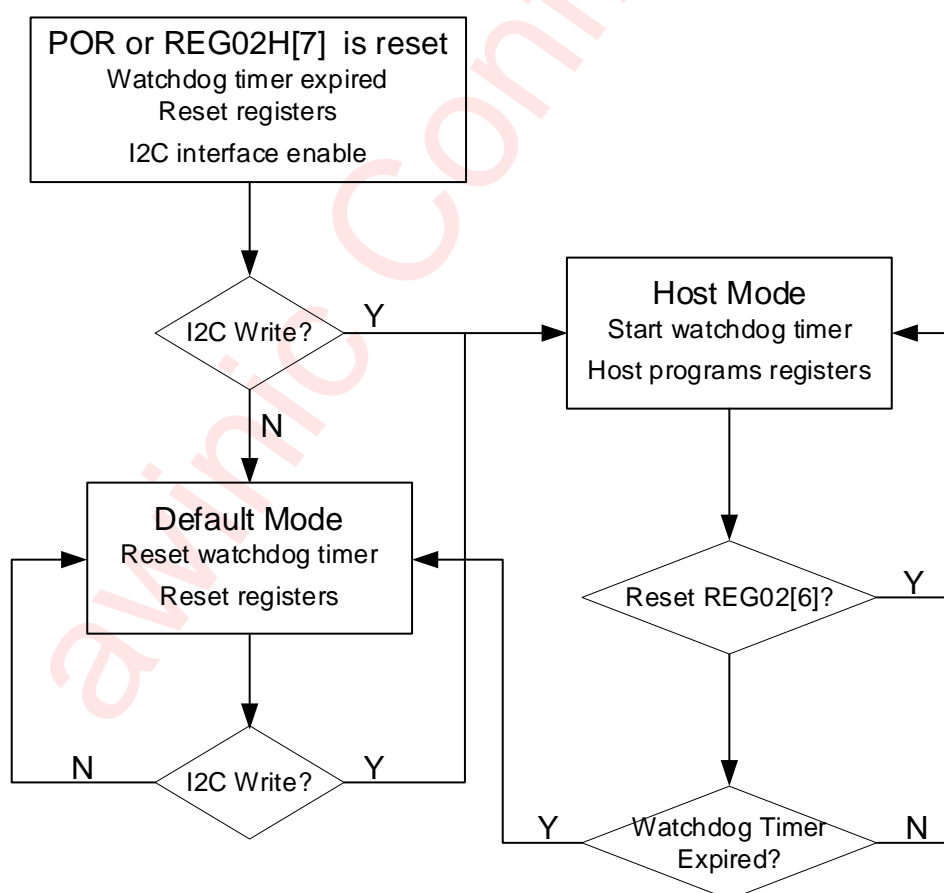


Figure 23 Watchdog Timer Flow Chart

## General I<sup>2</sup>C Operation

The device supports the I<sup>2</sup>C serial bus and data transmission protocol. It operates as a slave on the I<sup>2</sup>C bus. The maximum clock frequency specified by the I<sup>2</sup>C standard is 400kHz. Connect to the bus are made via the open-drain I/O pins SCL and SDA. The pull-up resistor can be selected in the range of 1k~10kΩ and the typical value is 4.7kΩ when I<sup>2</sup>C frequency is 400kHz. Different high level from 1.2V to 5V of this I<sup>2</sup>C interface is supported.

### Device Address

AW32002 7-bit slave address (A7~A1) is 1001001 binary(0x49H). After the START condition, the I<sup>2</sup>C master sends the 7-bit chip address followed by an eighth (A0) read or write bit (R/W). R/W= 0 indicates a WRITE function and R/W = 1 indicates a READ function.

Table 6: Device Address

A7	A6	A5	A4	A3	A2	A1	A0
1	0	0	1	0	0	1	R/W

### Data Validation

When SCL is high level, SDA level must be constant. SDA can be changed only when SCL is low level.

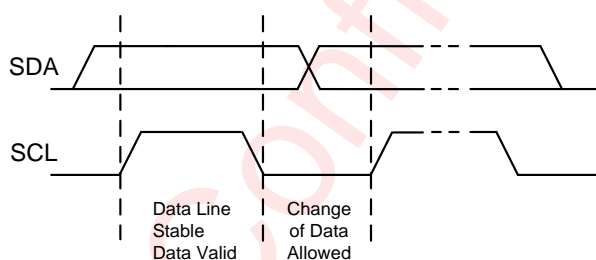


Figure 24 Data Validation Diagram

### I<sup>2</sup>C Start/Stop

I<sup>2</sup>C start: SDA changes from high level to low level when SCL is high level.

I<sup>2</sup>C stop: SDA changes from low level to high level when SCL is high level.

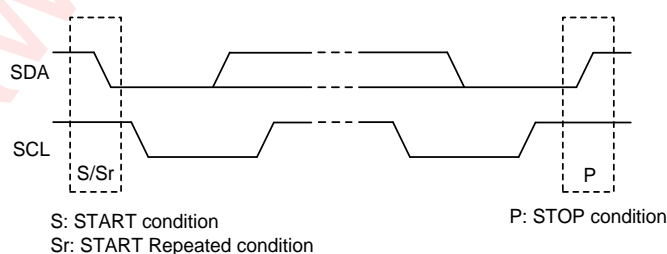


Figure 25 Start and Stop Conditions

### ACK (Acknowledgement)

ACK means the successful transfer of I<sup>2</sup>C bus data. After master sends 8bits data, SDA must be released; SDA is pulled to GND by slave device when slave acknowledges.

When master reads, slave device sends 8bit data, releases the SDA and waits for ACK from master. If ACK is send and I<sup>2</sup>C stop is not send by master, slave device sends the next data. If ACK is not send by master, slave device stops to send data and waits for I<sup>2</sup>C stop.

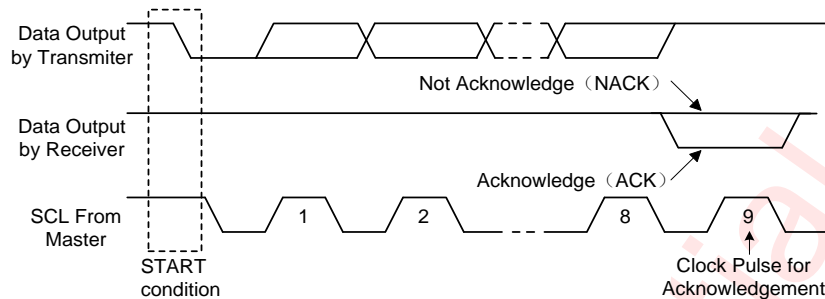


Figure 26 Acknowledgement Diagram

### Write Process

One data bit is transferred during each clock pulse. Data is sampled during the high state of the serial clock (SCL). Consequently, throughout the clock's high period, the data should remain stable. Any changes on the SDA line during the high state of the SCL and in the middle of a transaction, aborts the current transaction. New data should be sent during the low SCL state. This protocol allows a single data line to transfer both command/control information and data using the synchronous serial clock.

Each data transaction is composed of a Start Condition, a number of byte transfers (set by the software) and a Stop Condition to terminate the transaction. Every byte written to the SDA bus must be 8 bits long and is transferred with the most significant bit first. After each byte, an Acknowledge signal must follow.

In a write process, the following steps should be followed:

- Master device generates START condition. The "START" signal is generated by lowering the SDA signal while the SCL signal is high.
- Master device sends slave address (7-bit) and the data direction bit ( $r/w = 0$ ).
- Slave device sends acknowledge signal if the slave address is correct.
- Master sends control register address (8-bit)
- Slave sends acknowledge signal
- Master sends data byte to be written to the addressed register
- Slave sends acknowledge signal
- If master will send further data bytes the control register address will be incremented by one after acknowledge signal (repeat steps f and g)
- Master generates STOP condition to indicate write cycle end

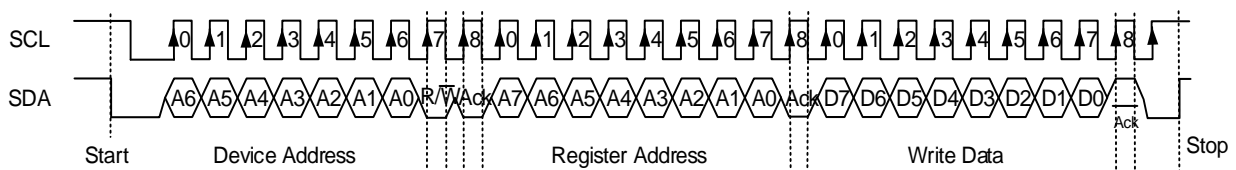


Figure 27 I<sup>2</sup>C Write Timing

**Read Process**

In a read cycle, the following steps should be followed:

- a) Master device generates START condition
- b) Master device sends slave address (7-bit) and the data direction bit ( $r/w = 0$ ).
- c) Slave device sends acknowledge signal if the slave address is correct.
- d) Master sends control register address (8-bit)
- e) Slave sends acknowledge signal
- f) Master generates STOP condition followed with START condition or REPEAT START condition
- g) Master device sends slave address (7-bit) and the data direction bit ( $r/w = 1$ ).
- h) Slave device sends acknowledge signal if the slave address is correct.
- i) Slave sends data byte from addressed register.
- j) If the master device sends acknowledge signal, the slave device will increase the control register address by one, then send the next data from the new addressed register.
- k) If the master device generates STOP condition, the read cycle is ended.

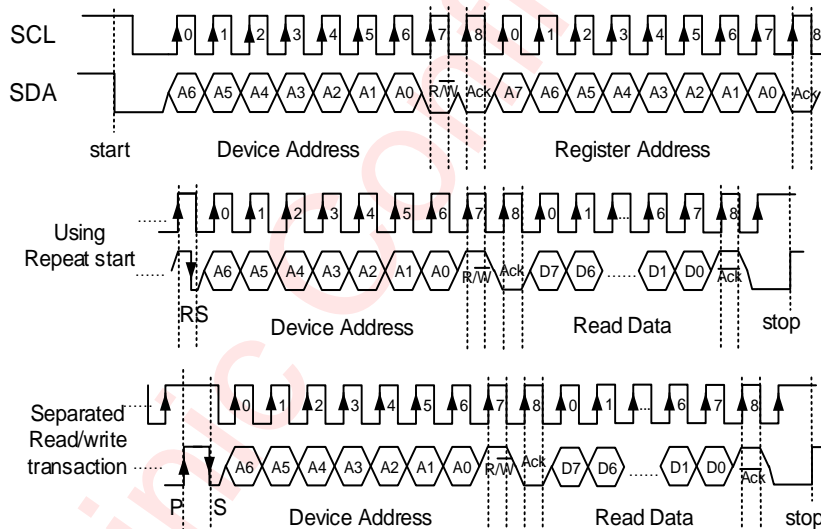


Figure 28 I<sup>2</sup>C Read Timing

## Register List

### Register Map

R/W = Read/Write, RC = Read Clear.

ADDR	0x00	0x01	0x02	0x03	0x04
NAME	Input Source Control	Power On Configuration	Charge Current Control	Discharge Current Control	Charge Voltage
Default	0x8F	0xAC	0x0F	0x91	0XA3
Bit7	VIN_DPM[3:0]	t <sub>RST_DGL</sub>	REG_RST	IDSCHG[3:0]	VBAT_REG[5:0]
Bit6			WD_TMR_RST		
Bit5		t <sub>RST_DUR</sub>	ICHG[5:0]		
Bit4		EN_HIZ			
Bit3	CEB	ITERM[3:0]			
Bit2	VBAT_UVLO[2:0]				
Bit1			IIN_LIM[3:0]		
Bit0					

ADDR	0x05	0x06	0x07	0x08
NAME	Charger Termination/Timer Control	Main Control	System Voltage Control	System Status
Default	0x7A	0xC0	0x38	0x40
Bit7	EN_WD_DISCHG	EN_NTC	DIS_PCB_OTP	Watchdog_Fault
Bit6	WATCHDOG[1:0]	TMR2X_EN	DIS_VINLOOP	Rev[1:0]
Bit5		FET_DIS	TJ_REG[1:0]	
Bit4	EN_TERM	PG_INT_CONTROL		VSYS_REG[3:0]
Bit3	EN_TIMER	EOC_INT_CONTROL	PPM_STAT	
Bit2	CHG_TMR[1:0]	CHG STATUS_INT_CONTROL	PG_STAT	
Bit1		NTC_INT_CONTROL	THERM_STAT	
Bit0	TERM_TMR	BATOV_P_INT_CONTROL		

ADDR	0x09	0x0A	0x0B	0x0C	0x22
NAME	Fault	Address	Individual Charge	Additional Function Control	Additional Function Control
Default	0x00	0x49	0x43	0x10	0x03
Bit7	EN_SHIPPING_DGL[1:0]	CHIPID[7:0]	Reserve	EN0P55	Reserve[3:0]
Bit6			Reserve	ITERMDEG	
Bit5	VIN_FAULT		EN_IPRE_SET	Reserve[1:0]	
Bit4	THEM_SD		IPRE[3:0]	PRETO	INT100MS
Bit3	BAT_FAULT			DIS_SHIPINT	Reserve[2:0]
Bit2	STMR_FAULT			Reserve	
Bit1	NTC_FAULT[1:0]		EN_SHIPMD_0P1S	RSTDLAY	
Bit0					

**Input Source Control Register**

Address: 00H, Reset State: 1000 1111.

BIT Name	W/R	BIT	SFTRST	WTDRST	Function
VIN_DPM	W/R	B7-B4	Y	N	VIN_DPM voltage regulation setting: BIN VIN_DPM (V) 0000 3.88 <b>1000 4.52 (default)</b> 0001 3.96 1001 4.60 0010 4.04 1010 4.68 0011 4.12 1011 4.76 0100 4.20 1100 4.84 0101 4.28 1101 4.92 0110 4.36 1110 5.00 0111 4.44 1111 5.08
IIN_LIM	W/R	B3-B0	Y	N	Input current limit setting: BIN IIN_LIM (mA) 0000 50 1000 290 0001 80 1001 320 0010 110 1010 350 0011 140 1011 380 0100 170 1100 410 0101 200 1101 440 0110 230 1110 470 0111 260 <b>1111 500(default)</b>

**Power On Configuration Register**

Address: 01H, Reset State: 1010 1100.

BIT Name	W/R	BIT	SFTRST	WTDRST	Function
$t_{RST\_DGL}$	W/R	B7-B6	Y	Y	Pull INT low time period to disconnect the battery: BIN time (s) 00: 8 01: 12 <b>10: 16(default) 11: 20</b>
$t_{RST\_DUR}$	W/R	B5	Y	Y	Q2 lasts off time before auto-on: 0: 2s; <b>1: 4s (default).</b>
EN_HIZ	W/R	B4	Y	Y	<b>0: disable (default); 1: enable.</b>
CEB	W/R	B3	Y	Y	0: charge enable; <b>1: charge disable (default).</b>
VBAT_UVLO	W/R	B2-B0	Y	Y	Battery UVLO Threshold: BIN VBAT_UVLO (V) 000 2.43 <b>100 2.76 (default)</b> 001 2.49 101 2.85 010 2.58 110 2.94 011 2.67 111 3.03

**Charge Current Control Register**

Address: 02H, Reset State:0000 1111

BIT Name	W/R	BIT	REGRST	WTDRST	Function
REG_RST	W/R	B7	Y	N	<b>0: keep current setting (default); 1: reset.</b>
WD_TMR_RST	W/R	B6	Y	Y	<b>0: normal (default); 1: reset.</b>
ICHG	W/R	B5-B0	Y	Y	Fast charge current setting: BIN ICHG(mA) 000000 8 100000 264 000001 16 100001 272 000010 24 100010 280 000011 32 100011 288 000100 40 100100 296 000101 48 100101 304 000110 56 100110 312 000111 64 100111 320 001000 72 101000 328 001001 80 101001 336 001010 88 101010 344 001011 96 101011 352 001100 104 101100 360 001101 112 101101 368 001110 120 101110 376 <b>001111 128 (default) 101111 384</b> 010000 136 110000 392 010001 144 110001 400 010010 152 110010 408 010011 160 110011 416 010100 168 110100 424 010101 176 110101 432 010110 184 110110 440 010111 192 110111 448 011000 200 111000 456 011001 208 setting REG0CH[7]=1 and 011010 216 REG00H[3:0]=1111, open 011011 224 111001 464 011100 232 111010 472 011101 240 111011 480 011110 248 111100 488 011111 256 111101 496 111110 504 111111 512

**Discharge Current Control Register**

Address: 03H, Reset State1001 0001.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
IDSCHG	W/R	B7-B4	Y	Y	BAT to SYS discharge current limit: BIN IDSCHG(mA) 0000 200 1000 1800 0001 400 <b>1001 2000 (default)</b> 0010 600 1010 2200 0011 800 1011 2400 0100 1000 1100 2600 0101 1200 1101 2800 0110 1400 1110 3000 0111 1600 1111 3200

ITERM	W/R	B3-B0	Y	Y	Termination current. current range:			
					BIN	ITERM(mA)		
					0000	1	1000	17
					<b>0001</b>	<b>3 (default)</b>	1001	19
					0010	5	1010	21
					0011	7	1011	23
					0100	9	1100	25
					0101	11	1101	27
					0110	13	1110	29
					0111	15	1111	31

**Charge Voltage Register**

Address: 04H, Reset State:1010 0011.

BIT Name	W/R	BIT	REGRST	WDRST	Function			
VBAT_REG	W/R	B7-B2	Y	Y	Battery regulation voltage:			
					BIN	VBAT_REG(V)		
					000000	3.600	100000	4.080
					000001	3.615	100001	4.095
					000010	3.630	100010	4.110
					000011	3.645	100011	4.125
					000100	3.660	100100	4.140
					000101	3.675	100101	4.155
					000110	3.690	100110	4.170
					000111	3.705	100111	4.185
					001000	3.720	<b>101000</b>	<b>4.200(default)</b>
					001001	3.735	101001	4.215
					001010	3.750	101010	4.230
					001011	3.765	101011	4.245
					001100	3.780	101100	4.260
					001101	3.795	101101	4.275
					001110	3.810	101110	4.290
					001111	3.825	101111	4.305
					010000	3.840	110000	4.320
					010001	3.855	110001	4.335
					010010	3.870	110010	4.350
					010011	3.885	110011	4.365
					010100	3.900	110100	4.380
					010101	3.915	110101	4.395
					010110	3.930	110110	4.410
					010111	3.945	110111	4.425
					011000	3.960	111000	4.440
					011001	3.975	111001	4.455
					011010	3.990	111010	4.470
					011011	4.005	111011	4.485
011100	4.020	111100	4.500					
011101	4.035	111101	4.515					
011110	4.050	111110	4.530					
011111	4.065	111111	4.545					
VBAT_PRE	W/R	B1	Y	Y	Pre-charge to Fast charge threshold: 0: 2.8V; <b>1: 3.0V (default).</b>			
VRECH	W/R	B0	Y	Y	Battery recharge threshold (below VBAT_REG): 0: 100mV; <b>1: 200mV (default).</b>			

**Charger Termination/Timer Control Register**

Address: 05H, Reset State:0111 1010.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
EN_WD_DISC HG	W/R	B7	Y	N	Watchdog control in discharge mode: <b>0: disable (default); 1: enable.</b>
WATCHDOG	W/R	B6-B5	Y	N	Watchdog setting: 00: disable timer    01: 40s 10: 80s <b>11: 160s (default)</b> If Bit[6:5]=00, then watchdog timer is disable no matter Bit 7 is set or no.
EN_TERM	W/R	B4	Y	Y	Termination Setting (control the termination is allowed or not): <b>0: disable ; 1: enable (default).</b>
EN_TIMER	W/R	B3	Y	Y	Safety timer Setting: <b>0: disable; 1: enable (default).</b>
CHG_TMR	W/R	B2-B1	Y	Y	Fast charge timer: 00: 3hrs <b>01: 5hrs (default);</b> 10: 8hrs                11: 12hrs.
TERM_TMR	W/R	B0	Y	Y	Termination timer Setting: <b>0: disable (default); 1: enable.</b>

**Main Control Register**

Address: 06H, Reset State:1100 0000.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
EN_NTC	W/R	B7	Y	Y	<b>0: disable ; 1: enable (default).</b>
TMR2X_EN	W/R	B6	Y	Y	<b>0: disable 2x extended safety timer during PPMF;</b> <b>1: enable 2x extended safety timer during PPMF</b> <b>(default).</b>
FET_DIS	W/R	B5	Y	N	<b>0: enable (default); 1: turn off.</b>
PG_INT_CON TROL	W/R	B4	Y	Y	<b>0: on (default); 1: off.</b>
EOC_INT_CO NTROL	W/R	B3	Y	Y	<b>0: on (default); 1: off. (EOC: End of Charge)</b>
CHG STATUS_INT _CONTROL	W/R	B2	Y	Y	<b>0: on (default); 1: off.</b>
NTC_INT_CO NTROL	W/R	B1	Y	Y	<b>0: on (default); 1: off.</b>
BATOVP_INT _CONTROL	W/R	B0	Y	Y	<b>0: on (default); 1: off.</b>

**System Voltage Control Register**

Address: 07H, Reset State:0011 1000.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
DIS_PCB_OTP	W/R	B7	Y	Y	PCB OTP Disable. <b>0: enable PCB OTP (default); 1: disable PCB OTP.</b>
DIS_VINLOOP	W/R	B6	Y	Y	VIN_DPM loop. <b>0: enable VIN_DPM loop (default); 1: disable.</b>
TJ_REG	W/R	B5-B4	Y	Y	Thermal regulation threshold: BIN    Temperature(°C) 00    60                01    80 10    100              11 <b>120 (default)</b>

VSYS_REG	W/R	B3-B0	Y	N	System voltage regulation. Range:
					BIN VSYS_REG(V)
					0000 4.20 <b>1000 4.60 (default)</b>
					0001 4.25      1001 4.65
					0010 4.30      1010 4.70
					0011 4.35      1011 4.75
					0100 4.40      1100 4.80
					0101 4.45      1101 4.85
					0110 4.50      1110 4.90
0111 4.55      1111 4.95					

**System Status Register**

Address: 08H, Reset State:0100 0000.

BIT Name	W/R	BIT	REG RST	WTDRST	Function
Watchdog_Fault	R	B7	NA	NA	<b>0: normal (default);</b> 1: watchdog timer expiration.
Rev	R	B6-B5	NA	NA	
CHG_STAT	R	B4-B3	NA	NA	<b>00: not charging (default);</b> 01: pre charge; 10: charge; 11: charge done.
PPM_STAT	R	B2	NA	NA	<b>0: no PPM (default);</b> 1: IN PPM.
PG_STAT	R	B1	NA	NA	0: Power fail; 1: Power good.
THERM_STAT	R	B0	NA	NA	<b>0: no thermal regulation (default);</b> 1: in thermal regulation.

**Fault Register**

Address: 09H, Reset State:0000 0000.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
EN_SHIPPING_DGL	W/R	B7-B6	Y	N	Enter shipping mode deglitch time: BIN deglitch time(s) <b>00: 1 (default);</b> 01: 2 10: 4 11: 8
VIN_FAULT	R	B5	NA	NA	<b>0: normal (default);</b> 1: input fault (OVP or bad source).
THEM_SD	R	B4	NA	NA	<b>0: normal (default);</b> 1: thermal shutdown.
BAT_FAULT	R	B3	NA	NA	<b>0: normal (default);</b> 1: battery OVP.
STMR_FAULT	R	B2	NA	NA	<b>0: normal (default);</b> 1: safety timer expiration.
NTC_FAULT[1]	R	B1	NA	NA	<b>0: normal (default);</b> 1: NTC hot.
NTC_FAULT[0]	R	B0	NA	NA	<b>0: normal (default);</b> 1: NTC cool.

**Address Register**

Address: 0AH, Reset State:0100 1001.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
CHIP ID	R	B7-B0	N	N	Chip ID used to be identified

**Individual Charge Register**

Address: 0BH, Reset State:0100 0011.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
Reserve	NA	B7	NA	NA	NA
Reserve	NA	B6	NA	NA	NA
EN_IPRE_SET	W/R	B5	Y	Y	<b>0: IPRE is set by REG03H[4:1] (default);</b> 1: IPRE is set by REG0BH[4:1].
IPRE[3:0]	W/R	B4-B1	Y	Y	1mA~31mA pre-charge current configuration: 2 mA/step, <b>3mA (default)</b> . BIN IPRE(mA) 0000 1 1000 17 <b>0001 3(default)</b> 1001 19 0010 5 1010 21 0011 7 1011 23 0100 9 1100 25 0101 11 1101 27 0110 13 1110 29 0111 15 1111 31
EN_SHIPMD_0 P1S	W/R	B0	Y	Y	VIN Plug: In deglitch time of shipping mode out: 0: 2s; <b>1: 100ms(default)</b> .

**Additional Function Control Register**

Address: 0CH, Reset State:0001 0000.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
ENOP55	W/R	B7	Y	Y	Increase input current limit: <b>0: The input current limit is set by REG00H[3:0] (default);</b> 1: If REG00H[3:0]=1111,this bit increase the input current limit to 550mA, otherwise, it is useless.
ITERMDEG	W/R	B6	Y	Y	Charge termination current deglitch time: <b>0:3s (default);</b> 1:1s.
Reserve	NA	B5~B4	NA	NA	NA
PRETO	W/R	B3	Y	Y	<b>0: Pre-charge timeout is 1h (default);</b> 1: Pre-charge timeout is 2h.
DIS_SHIPINT	W/R	B2	Y	Y	The function of disabling INT PIN during SHIPPING mode: <b>0: Nominal INT PIN function(Default);</b> 1: Disable INT PIN function during SHIPPING mode.
Reserve	NA	B1	NA	NA	NA
RSTDLAY	W/R	B0	Y	Y	The delay time after VSYS is Reset: <b>0: 0s (Default);</b> 1: 2s.

**Additional Function Control Register1**

Address: 22H, Reset State:0000 0011.

BIT Name	W/R	BIT	REGRST	WTDRST	Function
Reserve	NA	B7~B4	NA	NA	NA
INT100MS	W/R	B3	Y	Y	INT 100ms exit shipping mode <b>0: 2s (default);</b> 1:100ms.
Reserve	NA	B2~B0	NA	NA	NA

## Application Information

### NTC FUNCTION

NTC pin is connected to the thermistor paralleled with a resistor  $R_{F2}$  to ground. Another resistor  $R_{F1}$  is connected to the VDD which is the chip's internal power supply voltage. The high temperature limit and low temperature limit can be varied by using different  $R_{F1}$  and  $R_{F2}$ . Illustrated in Figure 29, the off chip resistors must be connected as the blue part demonstrated. The resistance of  $R_{F1}$  and  $R_{F2}$  can be calculated by Equation (1) and Equation (2):

$$R_{F2} = \frac{(V_{COLD} - V_{HOT}) \times R_{NTCH} \times R_{NTCL}}{(V_{HOT} - V_{COLD} \times V_{HOT}) \times R_{NTCL} - (V_{COLD} - V_{COLD} \times V_{HOT}) \times R_{NTCH}} \quad (1)$$

$$R_{F1} = \frac{1 - V_{COLD}}{V_{COLD}} \times (R_{F2} // R_{NTCL}) \quad (2)$$

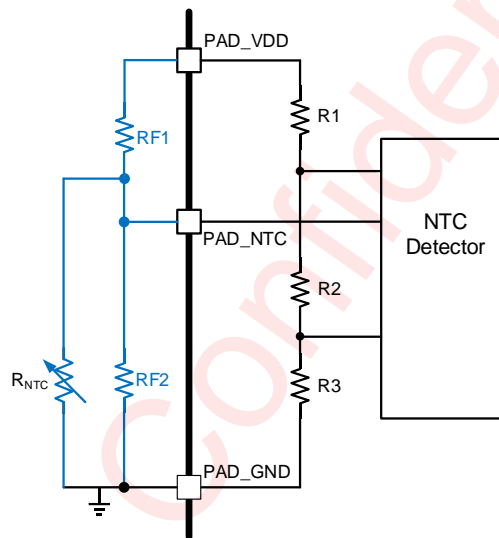


Figure 29 NTC Function(resistor-divided mode)

Where  $R_{NTCH}$  is the value of the NTC resistor at the high limit temperature, while the  $R_{NTCL}$  is the value of the NTC resistor at a low temperature limit.

## External Capacitor

The external capacitor cannot be absent for the operation of AW32002. Carefully selecting suitable capacitor is important to guarantee the AW32002 working perfectly on the space limited board.

A 4.7 $\mu$ F ceramic capacitor with high level voltage endurance (at least 30V) between IN and GND is recommended. This capacitor rejects input power supply ripple and enhance the stability of DPM loop.

A 1 $\mu$ F ceramic capacitor is required between the VDD and GND to maintain internal power supply voltage higher than the POR threshold. Without this capacitor, the chip logic block may work abnormally when working state changes.

Connect a ceramic capacitor between SYS and GND with least capacitance of 4.7 $\mu$ F to guarantee the stability of the system power supply loop. Larger capacitor will further reduce the system output's overshoot and undershoot.

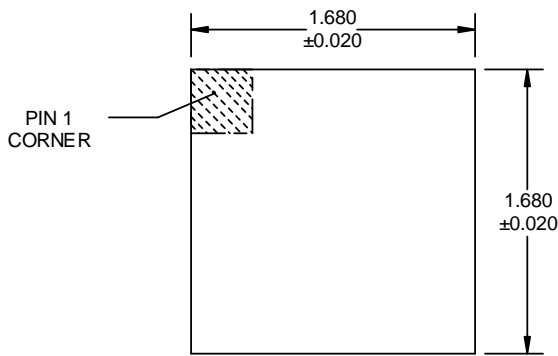
A least 4.7 $\mu$ F ceramic capacitor is also needed between BAT and GND for some application.

Table 7: Recommended external capacitors

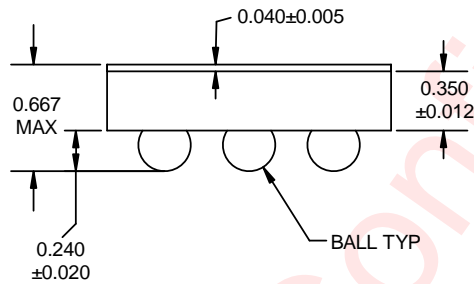
Comments	Capacitor	Supplier	Description	ELA Size	Effective Capacitance
C <sub>IN</sub>	4.7 $\mu$ F	Any	Ceramic Capacitor;50V; X5R or X7R	0603	>2 $\mu$ F
C <sub>VDD</sub>	0.1 $\mu$ F	Any	Ceramic Capacitor;16V; X5R or X7R	0603	>50nF
C <sub>SYS</sub>	4.7 $\mu$ F	Any	Ceramic Capacitor;16V; X5R or X7R	0603	>3 $\mu$ F
C <sub>BAT</sub>	4.7 $\mu$ F	Any	Ceramic Capacitor;16V; X5R or X7R	0603	>3 $\mu$ F



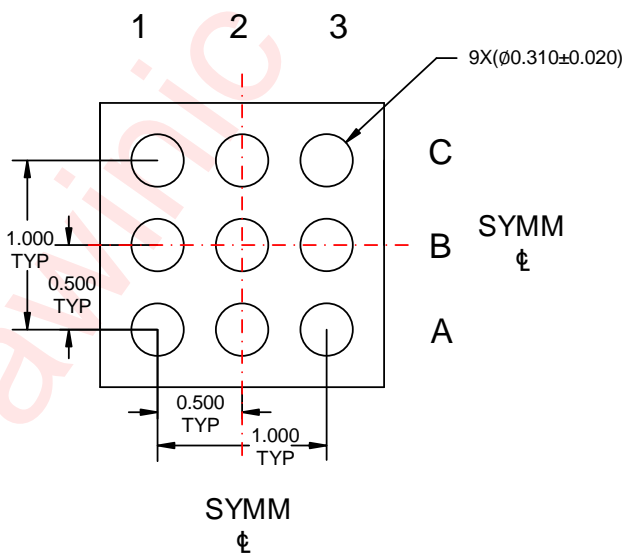
Package Description(POD)



Top View



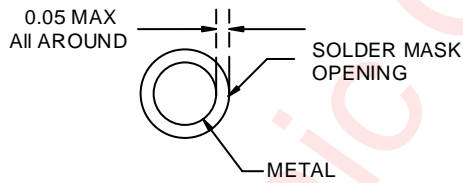
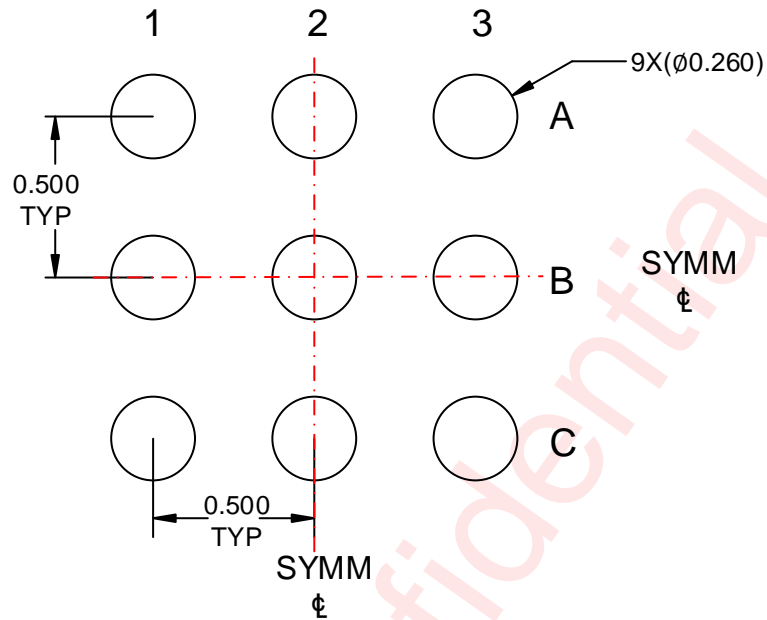
Side View



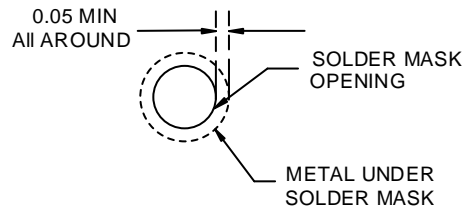
Bottom View

Unit: mm

Land Pattern Data



NON-SOLDER MASK DEFINED



SOLDER MASK DEFINED

Unit: mm

## Revision History

Version	Date	Change Record
V1.0	May 2020	Official Released
V1.1	Jun. 2020	<ol style="list-style-type: none"> <li>IEC62368-1 approved, File No.BE-37454. (P1)</li> <li>Deleted NTC related parameters. (P10)</li> </ol>
V1.2	Jan. 2021	<ol style="list-style-type: none"> <li>Change the description "Wide Range of Fast Charge Current: 8mA~456mA" to "Wide Range of Fast Charge Current: 8mA~512mA" (P1)</li> <li>Revise the Typical Application Circuit (P2) and Pin Definition (P3)</li> <li>Change the test condition of I<sub>Q_BAT</sub> "V<sub>IN</sub>=0, CEB=1, V<sub>BAT</sub>=4.35V, DIS_PCB_OTP=1, I<sub>SYS</sub>=0, enable watchdog" to "V<sub>IN</sub>=0, CEB=1, V<sub>BAT</sub>=4.35V, DIS_PCB_OTP=0, I<sub>SYS</sub>=0, enable watchdog". (P8)</li> <li>Add the maximum value of R<sub>ON_Q1</sub>, R<sub>ON_Q2</sub>, I<sub>IN_Q</sub> and I<sub>BAT_Q</sub> (P8)</li> <li>Add NTC related parameters. (P10)</li> <li>Add the 0CH register Bit[5] description.(P33)</li> <li>Add the 22H register description.(P34)</li> </ol>
V1.3	Jan. 2021	Add the Ichg=2mA and it's specialized range.(P9)
V1.4	May. 2021	Add the exit time of shipping mode.(P10)
V1.5	May. 2022	<ol style="list-style-type: none"> <li>Changed V<sub>BAT_REG</sub>=4.38V, REG04H[7:2]=110100 to 110010 in EC table</li> <li>Changed V<sub>SYS_REG</sub> test condition from "V<sub>IN</sub>=5.5V, EN_HIZ=0, R<sub>SYS</sub>=100Ω, I<sub>CHG</sub>=0A, V<sub>SYS_REG</sub>=4.6V" to "V<sub>IN</sub>=5.0V, REG07H[3:0]=0000, R<sub>SYS</sub>=100Ω, I<sub>CHG</sub>=0A, V<sub>SYS_REG</sub>=4.6V", added V<sub>SYS_REG</sub>=4.2V and V<sub>SYS_REG</sub>=4.95V test condition description.</li> <li>Changed deglitch time V<sub>RECH</sub> for test condition from "V<sub>BAT</sub> falling after charge termination" to "V<sub>BAT</sub> falling below V<sub>RECH</sub> after charge termination"</li> <li>Added T<sub>DGL_UVLO</sub>, T<sub>DGL_OVP</sub> and I<sub>LKG_INT</sub> parameter in EC table.</li> <li>Changed the parameter V<sub>SYS</sub> name to V<sub>SYS_REG</sub> in EC table</li> <li>Changed the parameter V<sub>IN_MIN</sub> name to V<sub>IN_DPM</sub> and V<sub>IN_DPM</sub> in EC table.</li> <li>Changed the parameter I<sub>IN_LMT</sub> name to I<sub>IN_LIM</sub> and I<sub>IN_LIM</sub> in EC table.</li> <li>Changed the parameter V<sub>OL(STAT)</sub> name to V<sub>OL(INT)</sub> in EC table.</li> <li>Added Register Map.</li> <li>Changed the REG22H default value from 00000000 to 00000011.</li> <li>Added NTC current mode description.</li> <li>Added Table 6: Recommended external capacitors.</li> <li>Other detail description.</li> <li>Change the Supply current I<sub>IN</sub> and Charge current I<sub>CHG</sub> value of Recommended Operating Conditions.</li> <li>Changed the condition of V<sub>SYS_REG</sub> definition that "V<sub>IN</sub>=5.3V, REG07H[3:0]=1111, R<sub>SYS</sub>=100Ω, I<sub>CHG</sub>=0A, V<sub>SYS_REG</sub>=4.6V" to "V<sub>IN</sub>=5.3V, REG07H[3:0]=1111, R<sub>SYS</sub>=100Ω, I<sub>CHG</sub>=0A, V<sub>SYS_REG</sub>=4.95V".</li> <li>Changed REG0BH[7], REG0CH[2] and REG0CH[1] in the REG MAP, and REG0CH[1] in the register description.</li> </ol>

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